

SSD1309

Advance Information

**128 x 64 Dot Matrix
OLED/PLED Segment/Common Driver with Controller**

This document contains information on a new product. Specifications and information herein are subject to change without notice.

Appendix: IC Revision history of SSD1309 Specification

Version	Change Items	Effective Date
0.10	1 st Release	12-Oct-10
1.0	1. Changed to Advance Information 2. Add SSD1309UR1 in ordering information. (P.11 , P.55)	14-Oct-10
1.1	1. Added Command 26h/27h/29h/2Ah/2Eh/2Fh/A3h/DCh in Section 9 & Section 10 (P.28~31, P.33, P.45~48) 2. Revised default value of A[7:4] of command D5h in Table 9-5 from 1000b into 0111b. (P.34)	25-Jul-11

CONTENT

1	GENERAL DESCRIPTION	7
2	FEATURES.....	7
3	ORDERING INFORMATION	7
4	BLOCK DIAGRAM.....	8
5	DIE PAD FLOOR PLAN.....	9
6	PIN ARRANGEMENT.....	11
6.1	SSD1309UR1 PIN ASSIGNMENT	11
7	PIN DESCRIPTION	13
8	FUNCTIONAL BLOCK DESCRIPTIONS.....	15
8.1	MCU INTERFACE SELECTION.....	15
8.1.1	MCU Parallel 6800-series Interface.....	15
8.1.2	MCU Parallel 8080-series Interface.....	16
8.1.3	MCU Serial Interface (4-wire SPI)	17
8.1.4	MCU Serial Interface (3-wire SPI)	18
8.1.5	MCU I ² C Interface	19
8.2	COMMAND DECODER	22
8.3	OSCILLATOR CIRCUIT AND DISPLAY TIME GENERATOR.....	22
8.4	RESET CIRCUIT	23
8.5	SEGMENT DRIVERS / COMMON DRIVERS	23
8.6	GRAPHIC DISPLAY DATA RAM (GDDRAM).....	24
8.7	SEG/COM DRIVING BLOCK	25
8.8	POWER ON AND OFF SEQUENCE	26
9	COMMAND TABLE	27
9.1	FUNDAMENTAL COMMAND TABLE	27
9.2	SCROLLING COMMAND TABLE	28
9.3	ADDRESSING SETTING COMMAND TABLE	32
9.4	HARDWARE CONFIGURATION (PANEL RESOLUTION & LAYOUT RELATED) COMMAND TABLE	33
9.5	TIMING & DRIVING SCHEME SETTING COMMAND TABLE	34
9.6	DATA READ / WRITE	35
10	COMMAND DESCRIPTIONS.....	36
10.1	SET LOWER COLUMN START ADDRESS FOR PAGE ADDRESSING MODE (00H~0FH)	36
10.2	SET HIGHER COLUMN START ADDRESS FOR PAGE ADDRESSING MODE (10H~1FH)	36
10.3	SET MEMORY ADDRESSING MODE (20H)	36
10.4	SET COLUMN ADDRESS (21H).....	37
10.5	SET PAGE ADDRESS (22H)	38
10.6	SET DISPLAY START LINE (40H~7FH)	38
10.7	SET CONTRAST CONTROL FOR BANK0 (81H)	38
10.8	SET SEGMENT RE-MAP (A0H/A1H).....	38
10.9	ENTIRE DISPLAY ON (A4H/A5H).....	38
10.10	SET NORMAL/INVERSE DISPLAY (A6H/A7H).....	39
10.11	SET MULTIPLEX RATIO (A8H)	39
10.12	SET DISPLAY ON/OFF (AEH/AFH)	39
10.13	SET PAGE START ADDRESS FOR PAGE ADDRESSING MODE (B0H~B7H)	39
10.14	SET COM OUTPUT SCAN DIRECTION (C0H/C8H).....	39
10.15	SET DISPLAY OFFSET (D3H)	39
10.16	SET DISPLAY CLOCK DIVIDE RATIO/ OSCILLATOR FREQUENCY (D5H).....	42
10.17	SET PRE-CHARGE PERIOD (D9H)	42
10.18	SET COM PINS HARDWARE CONFIGURATION (DAH).....	42
10.19	SET V _{COMH} DESELECT LEVEL (DBH).....	45

10.20	SET GPIO (DCH).....	45
10.21	NOP (E3H)	45
10.22	SET COMMAND LOCK (FDH)	45
10.23	HORIZONTAL SCROLL SETUP (26H/27H).....	45
10.24	CONTINUOUS VERTICAL AND HORIZONTAL SCROLL SETUP (29H/2AH)	46
10.25	DEACTIVATE SCROLL (2EH)	48
10.26	ACTIVATE SCROLL (2FH)	48
10.27	SET VERTICAL SCROLL AREA (A3H).....	48
10.28	CONTENT SCROLL SETUP (2CH/2DH).....	48
11	MAXIMUM RATINGS	51
12	DC CHARACTERISTICS	52
13	AC CHARACTERISTICS	53
14	APPLICATION EXAMPLE	59
15	PACKAGE INFORMATION	60
15.1	SSD1309Z DIE TRAY INFORMATION.....	60
15.2	SSD1309UR1 DETAIL DIMENSION	61

FIGURES

Figure 4-1 : SSD1309 Block Diagram.....	8
Figure 5-1: SSD1309Z Die Drawing	9
Figure 5-2: SSD1309Z alignment mark dimension	9
Figure 6-1 : SSD1309UR1 Pin Assignment	11
Figure 8-1 : Data read back procedure - insertion of dummy read	16
Figure 8-2 : Example of Write procedure in 8080 parallel interface mode	16
Figure 8-3 : Example of Read procedure in 8080 parallel interface mode	16
Figure 8-4 : Display data read back procedure - insertion of dummy read.....	17
Figure 8-5 : Write procedure in 4-wire Serial interface mode	18
Figure 8-6 : Write procedure in 3-wire Serial interface mode	18
Figure 8-7 : I ² C-bus data format	20
Figure 8-8 : Definition of the Start and Stop Condition.....	21
Figure 8-9 : Definition of the acknowledgement condition	21
Figure 8-10 : Definition of the data transfer condition	21
Figure 8-11 : Oscillator Circuit and Display Time Generator	22
Figure 8-12 : Segment Output Waveform in three phases	23
Figure 8-13 : GDDRAM pages structure of SSD1309	24
Figure 8-14 : Enlargement of GDDRAM (No row re-mapping and column-remapping)	24
Figure 8-15 : I _{REF} Current Setting by Resistor Value.....	25
Figure 8-16 : The Power ON sequence	26
Figure 8-17 : The Power OFF sequence	26
Figure 10-1 : Address Pointer Movement of Page addressing mode	36
Figure 10-2 : Example of GDDRAM access pointer setting in Page Addressing Mode (No row and column-remapping)	36
Figure 10-3 : Address Pointer Movement of Horizontal addressing mode.....	37
Figure 10-4 : Address Pointer Movement of Vertical addressing mode	37
Figure 10-5: Example of Column and Row Address Pointer Movement (LS pin pulled LOW)	38
Figure 10-6 : Transition between different modes	39
Figure 10-7: Horizontal scroll example: Scroll RIGHT by 1 column.....	45
Figure 10-8: Horizontal scroll example: Scroll LEFT by 1 column	46
Figure 10-9: Horizontal scrolling setup example (LS pin pull LOW)	46
Figure 10-10: Continuous Vertical scrolling setup example (LS pin pull LOW)	47
Figure 10-11: Continuous Vertical and Horizontal scrolling setup example (LS pin pull LOW)	48
Figure 10-12: Content Scrolling example (2Dh, Left Horizontal Scroll by one column).....	49
Figure 13-1 : 6800-series MCU parallel interface characteristics.....	54
Figure 13-2 : 8080-series parallel interface characteristics.....	55
Figure 13-3 : Serial interface characteristics (4-wire SPI).....	56
Figure 13-4 : Serial interface characteristics (3-wire SPI).....	57
Figure 13-5 : I ² C interface Timing characteristics	58
Figure 14-1 : Application Example of SSD1309Z.....	59
Figure 15-1: SSD1309Z die tray information	60
Figure 15-2 SSD1309UR1 Detail Dimension.....	61

TABLE

Table 3-1: Ordering Information	7
Table 5-1: SSD1309Z Bump Die Pad Coordinates	10
Table 6-1 : SSD1309UR1 Pin Assignment Table.....	12
Table 7-1 : SSD1309 Pin Description.....	13
Table 7-2 : Bus Interface selection	13
Table 8-1 : MCU interface assignment under different bus interface mode	15
Table 8-2 : Control pins of 6800 interface.....	15
Table 8-3 : Control pins of 8080 interface.....	17
Table 8-4 : Control pins of 4-wire Serial interface	17
Table 8-5 : Control pins of 3-wire Serial interface	18
Table 9-1: Fundamental Command Table	27
Table 9-2: Scrolling Command Table.....	28
Table 9-3: Addressing Setting Command Table	32
Table 9-4: Hardware Configuration (Panel resolution & layout related) Command Table	33
Table 9-5: Timing & Driving Scheme Setting Command Table	34
Table 9-6 : Read Command Table	35
Table 9-7 : Address increment table (Automatic).....	35
Table 10-1: Example of Set Display Offset and Display Start Line without Remap.....	40
Table 10-2: Example of Set Display Offset and Display Start Line with Remap.....	41
Table 10-3 : COM Pins Hardware Configuration	42
Table 10-4 : Content Scrolling software flow example (Page addressing mode – command 20h, 02h).	49
Table 10-5 : Content Scrolling setting example (Vertical addressing mode – command 20h, 01h).....	50
Table 11-1 : Maximum Ratings (Voltage Referenced to V _{SS})	51
Table 12-1 : DC Characteristics.....	52
Table 13-1 : AC Characteristics.....	53
Table 13-2 : 6800-Series MCU Parallel Interface Timing Characteristics	54
Table 13-3 : 8080-Series MCU Parallel Interface Timing Characteristics	55
Table 13-4 : Serial Interface Timing Characteristics (4-wire SPI)	56
Table 13-5 : Serial Interface Timing Characteristics (3-wire SPI)	57
Table 13-6 : I ² C Interface Timing Characteristics	58

1 GENERAL DESCRIPTION

SSD1309 is a single-chip CMOS OLED/PLED driver with controller for organic / polymer light emitting diode dot-matrix graphic display system. It consists of 128 segments and 64 commons. This IC is designed for Common Cathode type OLED panel.

The SSD1309 embeds with contrast control, display RAM and oscillator, which reduces the number of external components and power consumption. It has 256-step brightness control. Data/Commands are sent from general MCU through the hardware selectable 6800/8080 series compatible Parallel Interface, I²C interface or Serial Peripheral Interface. It is suitable for many compact portable applications, such as mobile phone sub-display, MP3 player and calculator, etc.

2 FEATURES

- Resolution: 128 x 64 dot matrix panel
- Power supply
 - V_{DD} = 1.65V ~ 3.3V for IC logic
 - V_{CC} = 7.0V ~ 16.0V for Panel driving
- For matrix display
 - OLED driving output voltage, 16V maximum
 - Segment maximum source current: 320uA
 - Common maximum sink current: 40mA
 - 256 step contrast brightness current control
- Embedded 128 x 64 bit SRAM display buffer
- Pin selectable MCU Interfaces:
 - 8-bit 6800/8080-series parallel interface
 - 3 /4 wire Serial Peripheral Interface
 - I²C Interface
- Screen saving infinite content scrolling function
- Programmable Frame Rate
- Programmable Multiplexing Ratio
- Row Re-mapping and Column Re-mapping
- On-Chip Oscillator
- Chip layout for COG , COF
- Wide range of operating temperature: -40°C to 85°C

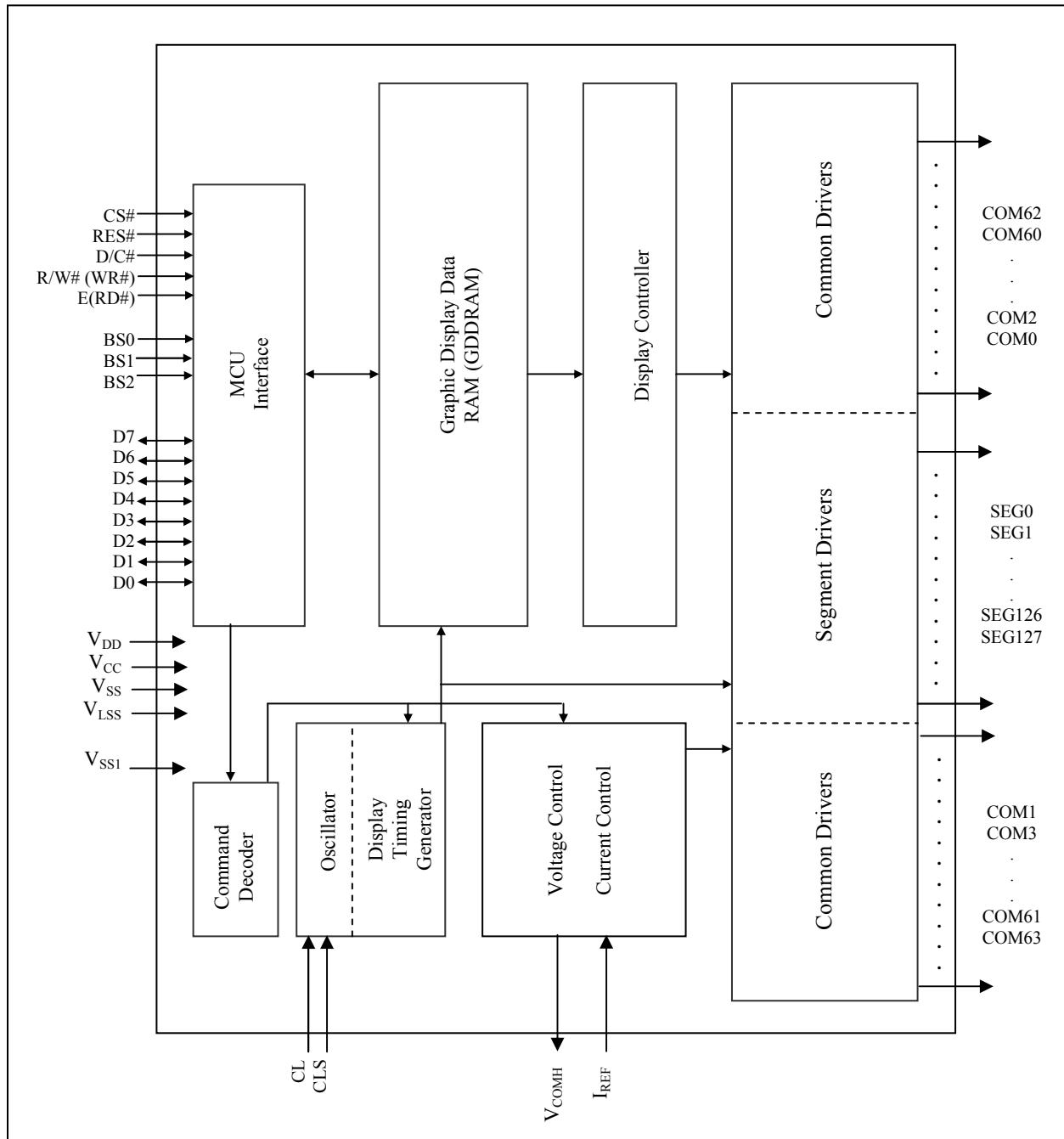
3 ORDERING INFORMATION

Table 3-1: Ordering Information

Ordering Part Number	SEG	COM	Package Form	Reference	Remark
SSD1309Z	128	64	COG	Page 9	<ul style="list-style-type: none">○ Min SEG pad pitch : 37.5um○ Min COM pad pitch : 27um○ Min I/O pad pitch : 60 um○ Die thickness : 300 +/- 15 um
SSD1309UR1	128	64	COF	Page 11,61	<ul style="list-style-type: none">○ 35mm film, 4 sprocket hole○ Hot bar type COF○ 8-bit 80 / 8-bit 68 / SPI / I2C interface○ SEG lead pitch 0.120mm x 0.998 =0.11976mm○ COM lead pitch 0.120mm x 0.998 =0.11976mm

4 BLOCK DIAGRAM

Figure 4-1 : SSD1309 Block Diagram



5 DIE PAD FLOOR PLAN

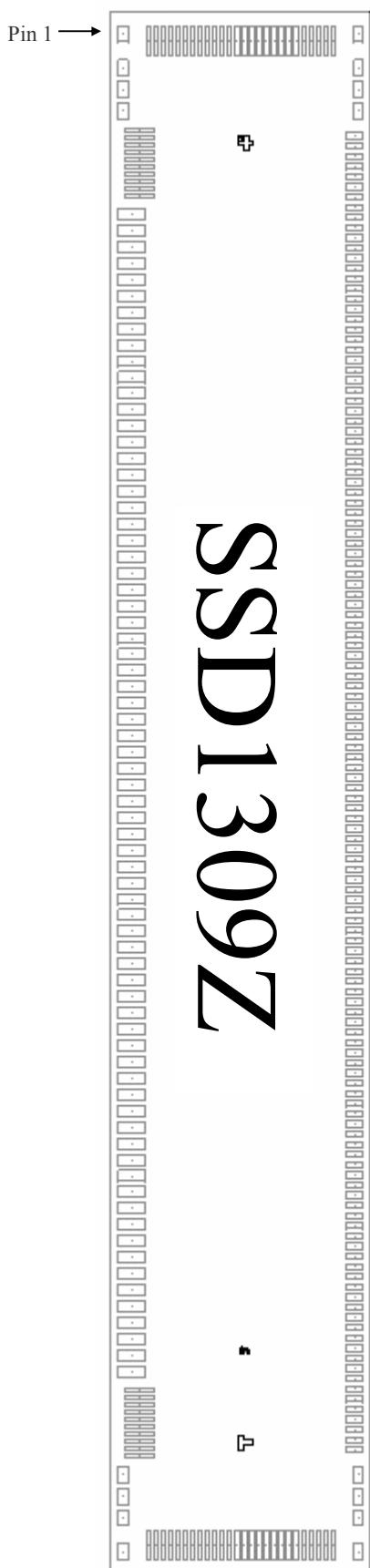


Figure 5-1: SSD1309Z Die Drawing

Die size (after sawing)	$5.8 \pm 0.05\text{mm} \times 1.0 \pm 0.05\text{mm}$
Die thickness	$300 \pm 15\mu\text{m}$
Min I/O pad pitch	60um
Min SEG pad pitch	37.5um
Min COM pad pitch	27um
Bump height	Nominal 12um

Bump size		
Pad#	X[um]	Y[um]
1~4, 97~100, 127~130, 261~264	59	35
5~14, 87~96	15	108
101~126, 265~290	108	15
15~86	40	100
131~260	22	64

Alignment mark	Position	Size
+ shape	(-2392.2, 18.8)	$56.25\mu\text{m} \times 56.25\mu\text{m}$
T shape	(2392.2, 18.8)	$56.25\mu\text{m} \times 56.25\mu\text{m}$
SSL Logo	(2055, 20)	-

(For details dimension please see Figure 5-2)

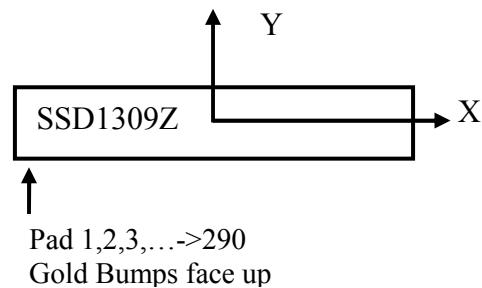
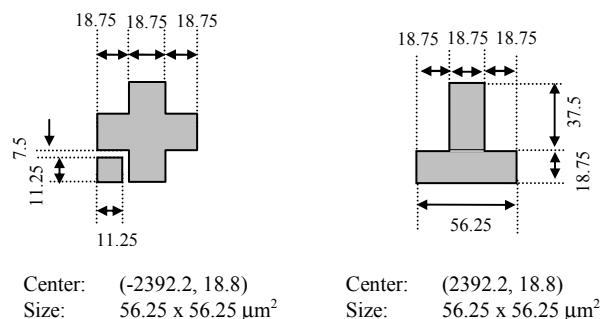


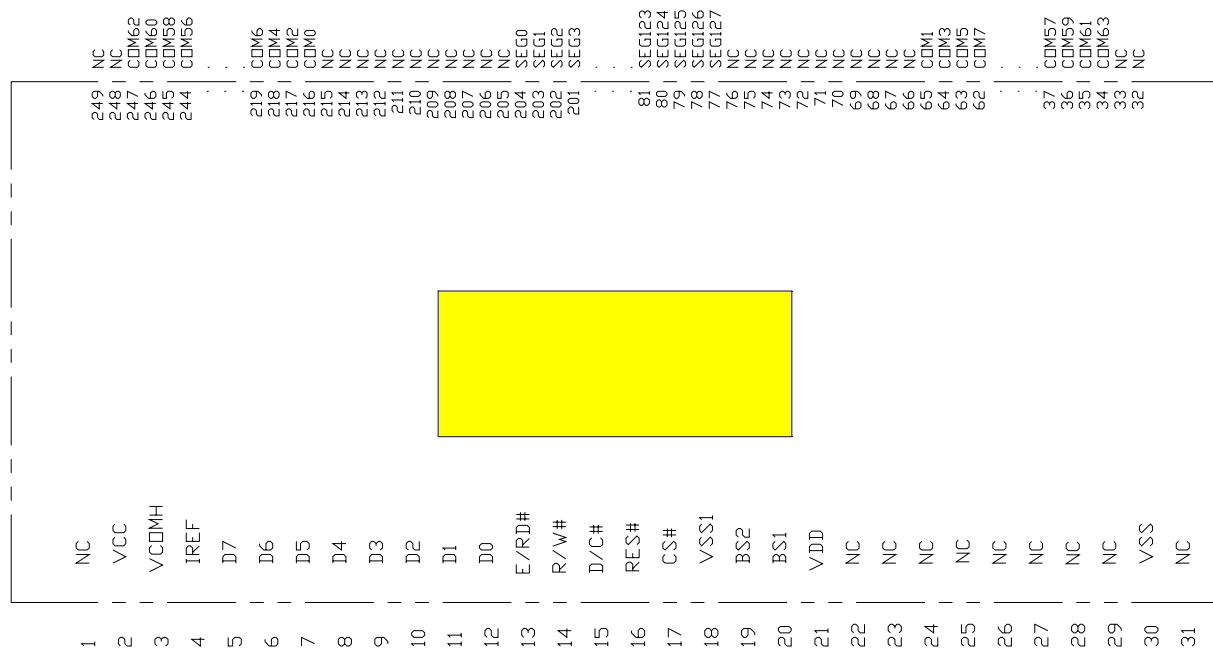
Figure 5-2: SSD1309Z alignment mark dimension



6 PIN ARRANGEMENT

6.1 SSD1309UR1 pin assignment

Figure 6-1 : SSD1309UR1 Pin Assignment



7 PIN DESCRIPTION

Key:

I = Input	NC = Not Connected
O = Output	Pull LOW= connect to Ground
I/O = Bi-directional (input/output)	Pull HIGH= connect to V _{DD}
P = Power pin	

Table 7-1 : SSD1309 Pin Description

Pin Name	Pin Type	Description												
V _{DD}	P	Power supply pin for core logic operation.												
V _{CC}	P	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.												
V _{SS}	P	Ground pin. It must be connected to external ground.												
V _{LSS}	P	Analog system ground pin. It must be connected to external ground.												
V _{SS1}	-	Reserved Pin. It must be connected to external ground.												
V _{COMH}	P	COM signal deselected voltage level. A capacitor should be connected between this pin and V _{SS} .												
BS[2:0]	I	MCU bus interface selection pins. Select appropriate logic setting as described in the following table. BS2, BS1 and BS0 are pin select. <p style="text-align: center;">Table 7-2 : Bus Interface selection</p> <table border="1"> <tr> <th>BS[2:0]</th> <th>Interface</th> </tr> <tr> <td>000</td> <td>4 line SPI</td> </tr> <tr> <td>001</td> <td>3 line SPI</td> </tr> <tr> <td>010</td> <td>I²C</td> </tr> <tr> <td>110</td> <td>8-bit 8080 parallel</td> </tr> <tr> <td>100</td> <td>8-bit 6800 parallel</td> </tr> </table> <p>Note</p> <p>⁽¹⁾ 0 is connected to V_{SS}</p> <p>⁽²⁾ 1 is connected to V_{DD}</p>	BS[2:0]	Interface	000	4 line SPI	001	3 line SPI	010	I ² C	110	8-bit 8080 parallel	100	8-bit 6800 parallel
BS[2:0]	Interface													
000	4 line SPI													
001	3 line SPI													
010	I ² C													
110	8-bit 8080 parallel													
100	8-bit 6800 parallel													
I _{REF}	I	This pin is the segment output current reference pin. I _{REF} is supplied externally. A resistor should be connected between this pin and V _{SS} to maintain the current around 10uA. Please refer to Figure 8-15 for the details of resistor value												
CL	I	This is external clock input pin. When internal clock is enabled (i.e. HIGH in CLS pin), this pin is not used and should be connected to V _{SS} . When internal clock is disabled (i.e. LOW in CLS pin), this pin is the external clock source input pin.												
CLS	I	This is internal clock enable pin. When it is pulled HIGH (i.e. connect to V _{DD}), internal clock is enabled. When it is pulled LOW, the internal clock is disabled; an external clock source must be connected to the CL pin for normal operation.												

Pin Name	Pin Type	Description
CS#	I	This pin is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW (active LOW).
RES#	I	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin pull HIGH during normal operation.
D/C#	I	This pin is Data/Command control pin connecting to the MCU. When the pin is pulled HIGH, the data at D[7:0] will be interpreted as data. When the pin is pulled LOW, the data at D[7:0] will be transferred to a command register. In I ² C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to V _{SS} . For detail relationship to MCU interface signals, refer to Timing Characteristics Diagrams Figure 13-1 to Figure 13-5
R/W# (WR#)	I	This pin is read / write control input pin connecting to the MCU interface. When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I ² C interface is selected, this pin must be connected to V _{SS} .
E (RD#)	I	This pin is MCU interface input. When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected. When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I ² C interface is selected, this pin must be connected to V _{SS} .
D[7:0]	I/O	These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I ² C mode is selected, D2, D1 should be tied together and serve as SDA _{out} , SDA _{in} in application and D0 is the serial clock input, SCL.
SEG0 ~ SEG127	O	These pins provide the OLED segment driving signals. These pins are V _{SS} state when display is OFF.
COM0 ~ COM63	O	These pins provide the Common switch signals to the OLED panel. These pins are in high impedance state when display is OFF.
TR[7:0]	-	Reserved pin and is recommended to keep it float.
NC	-	This is dummy pin. Do not group or short NC pins together.

8 FUNCTIONAL BLOCK DESCRIPTIONS

8.1 MCU Interface selection

SSD1309 MCU interface consist of 8 data pins and 5 control pins. The pin assignment at different interface mode is summarized in Table 8-1. Different MCU mode can be set by hardware selection on BS[2:0] pins (please refer to Table 7-2 for BS[2:0] setting).

Table 8-1 : MCU interface assignment under different bus interface mode

Pin Name Bus Interface	Data/Command Interface								Control Signal				
	D7	D6	D5	D4	D3	D2	D1	D0	E	R/W#	CS#	D/C#	RES#
8-bit 8080	D[7:0]								RD#	WR#	CS#	D/C#	RES#
8-bit 6800	D[7:0]								E	R/W#	CS#	D/C#	RES#
3-wire SPI	Tie LOW			NC	SDIN	SCLK	Tie LOW		CS#	Tie LOW		RES#	
4-wire SPI	Tie LOW			NC	SDIN	SCLK	Tie LOW		CS#	D/C#		RES#	
I ² C	Tie LOW			SDA _{OUT}	SDA _{IN}	SCL	Tie LOW			SA0	RES#		

8.1.1 MCU Parallel 6800-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), R/W#, D/C#, E and CS#.

A LOW in R/W# indicates WRITE operation and HIGH in R/W# indicates READ operation.

A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write.

The E input serves as data latch signal while CS# is LOW. Data is latched at the falling edge of E signal.

Table 8-2 : Control pins of 6800 interface

Function	E	R/W#	CS#	D/C#
Write command	↓	L	L	L
Read status	↓	H	L	L
Write data	↓	L	L	H
Read data	↓	H	L	H

Note

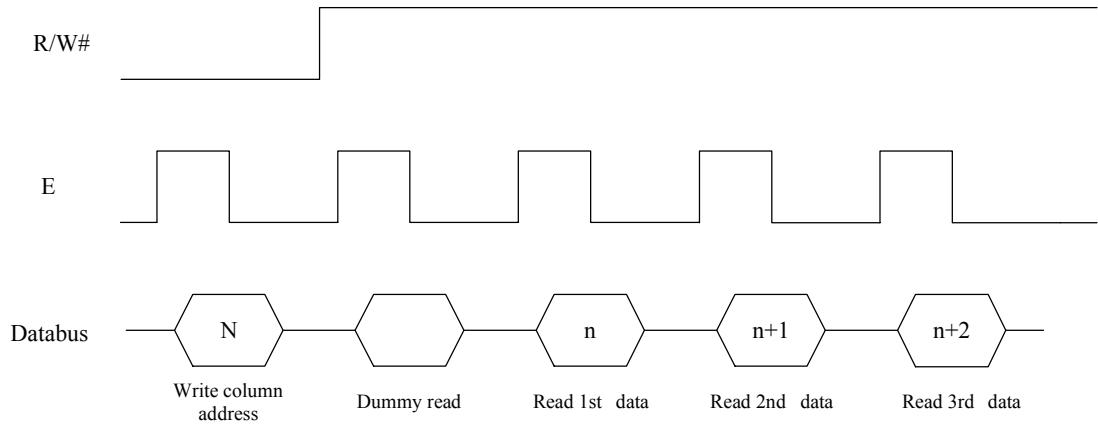
⁽¹⁾ ↓ stands for falling edge of signal

H stands for HIGH in signal

L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8-1.

Figure 8-1 : Data read back procedure - insertion of dummy read



8.1.2 MCU Parallel 8080-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), RD#, WR#, D/C# and CS#.

A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write.
A rising edge of RD# input serves as a data READ latch signal while CS# is kept LOW.
A rising edge of WR# input serves as a data/command WRITE latch signal while CS# is kept LOW.

Figure 8-2 : Example of Write procedure in 8080 parallel interface mode

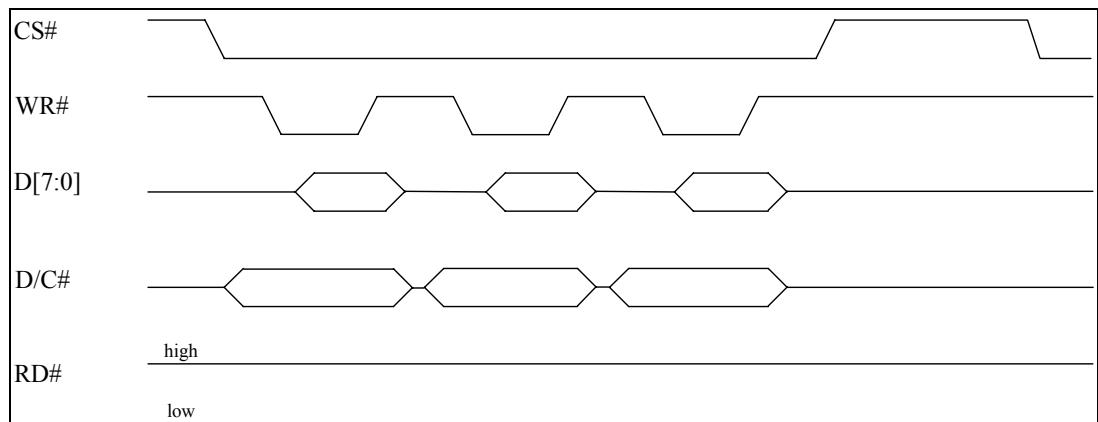


Figure 8-3 : Example of Read procedure in 8080 parallel interface mode

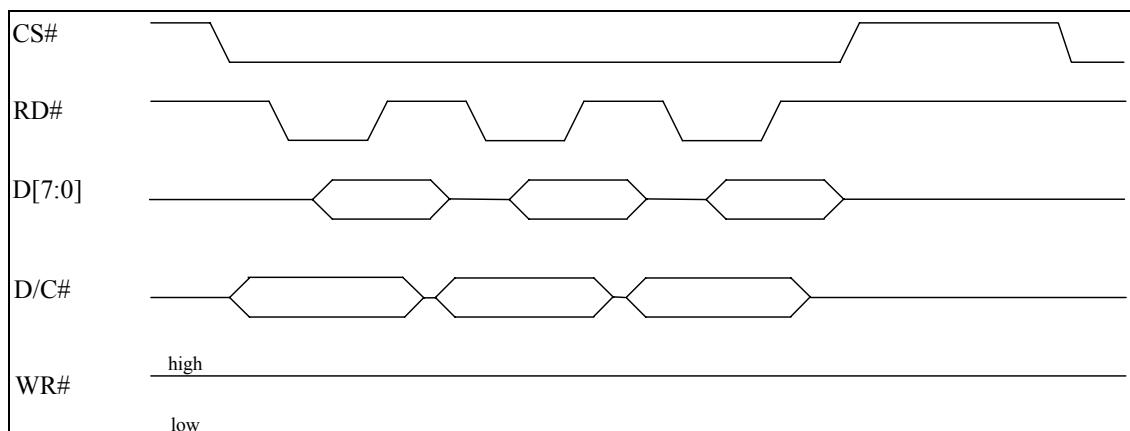


Table 8-3 : Control pins of 8080 interface

Function	RD#	WR#	CS#	D/C#
Write command	H	↑	L	L
Read status	↑	H	L	L
Write data	H	↑	L	H
Read data	↑	H	L	H

Note

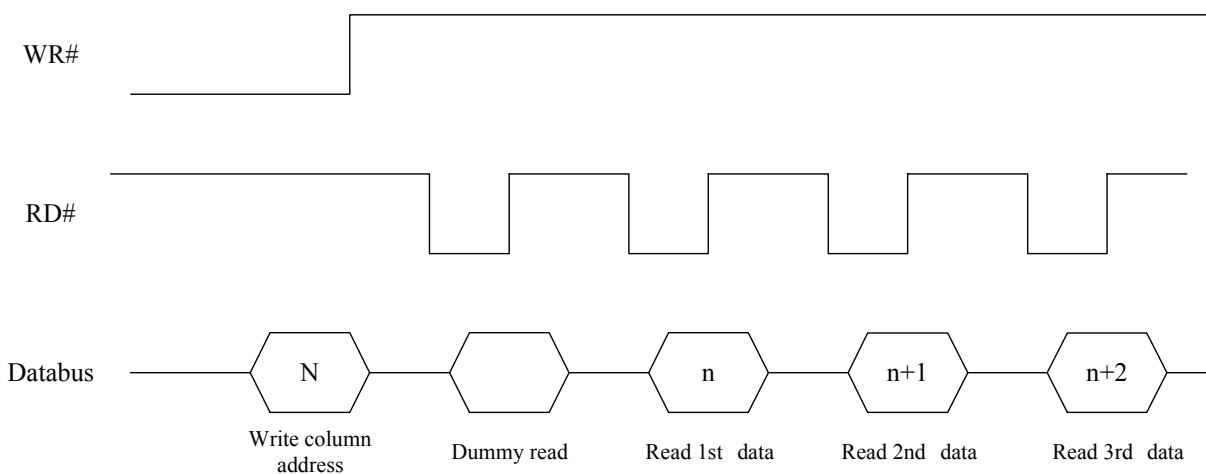
(¹) ↑ stands for rising edge of signal

(²) H stands for HIGH in signal

(³) L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8-4.

Figure 8-4 : Display data read back procedure - insertion of dummy read



8.1.3 MCU Serial Interface (4-wire SPI)

The 4-wire serial interface consists of serial clock: SCLK, serial data: SDIN, D/C#, CS#. In 4-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, E and R/W#(WR#/#) can be connected to an external ground.

Table 8-4 : Control pins of 4-wire Serial interface

Function	E	R/W#	CS#	D/C#	D0
Write command	Tie LOW	Tie LOW	L	L	↑
Write data	Tie LOW	Tie LOW	L	H	↑

Note

(¹) H stands for HIGH in signal

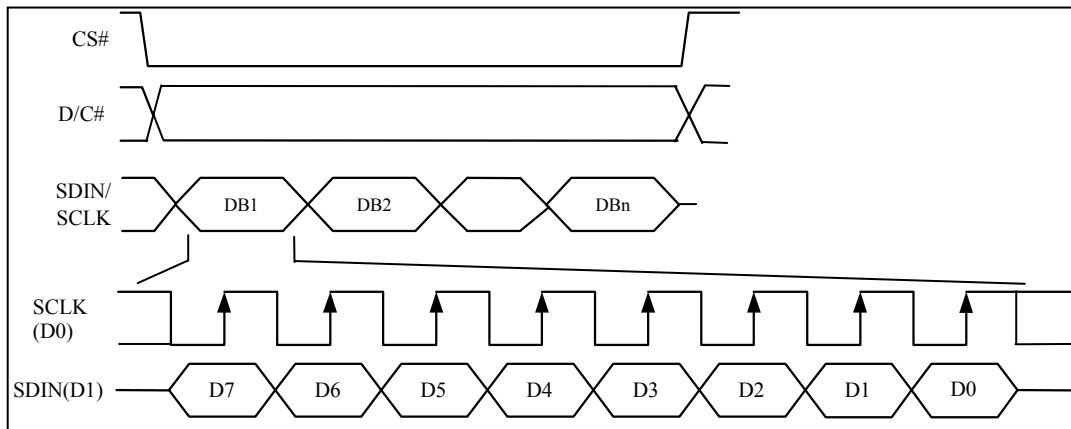
(²) L stands for LOW in signal

(³) ↑ stands for rising edge of signal

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D7, D6, ... D0. D/C# is sampled on every eighth clock and the data byte in the shift register is written to the Graphic Display Data RAM (GDDRAM) or command register in the same clock.

Under serial mode, only write operations are allowed.

Figure 8-5 : Write procedure in 4-wire Serial interface mode



8.1.4 MCU Serial Interface (3-wire SPI)

The 3-wire serial interface consists of serial clock SCLK, serial data SDIN and CS#.

In 3-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, R/W# (WR#), E and D/C# can be connected to an external ground.

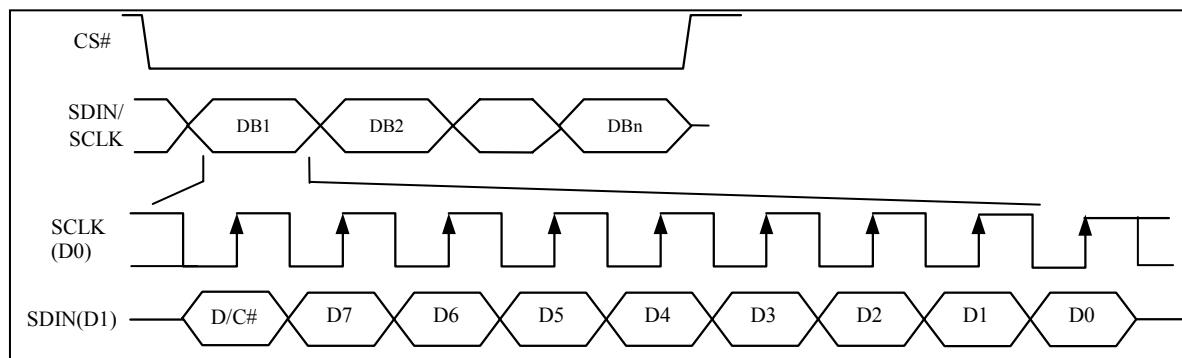
The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit. The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0).

Under serial mode, only write operations are allowed.

Table 8-5 : Control pins of 3-wire Serial interface

Function	E(RD#)	R/W#(WR#)	CS#	D/C#	D0	Note
Write command	Tie LOW	Tie LOW	L	Tie LOW	↑	⁽¹⁾ L stands for LOW in signal
Write data	Tie LOW	Tie LOW	L	Tie LOW	↑	⁽²⁾ ↑ stands for rising edge of signal

Figure 8-6 : Write procedure in 3-wire Serial interface mode



8.1.5 MCU I²C Interface

The I²C communication interface consists of slave address bit SA0, I²C-bus data signal SDA (SDA_{OUT}/D₂ for output and SDA_{IN}/D₁ for input) and I²C-bus clock signal SCL (D₀). Both the data and clock signals must be connected to pull-up resistors. RES# is used for the initialization of device.

a) Slave address bit (SA0)

SSD1309 has to recognize the slave address before transmitting or receiving any information by the I²C-bus. The device will respond to the slave address following by the slave address bit (“SA0” bit) and the read/write select bit (“R/W#” bit) with the following byte format,

b₇ b₆ b₅ b₄ b₃ b₂ b₁ b₀
0 1 1 1 1 0 SA0 R/W#

“SA0” bit provides an extension bit for the slave address. Either “0111100” or “0111101”, can be selected as the slave address of SSD1309. D/C# pin acts as SA0 for slave address selection.

“R/W#” bit is used to determine the operation mode of the I²C-bus interface. R/W#=1, it is in read mode. R/W#=0, it is in write mode.

b) I²C-bus data signal (SDA)

SDA acts as a communication channel between the transmitter and the receiver. The data and the acknowledgement are sent through the SDA.

It should be noticed that the ITO track resistance and the pulled-up resistance at “SDA” pin becomes a voltage potential divider. As a result, the acknowledgement would not be possible to attain a valid logic 0 level in “SDA”.

“SDA_{IN}” and “SDA_{OUT}” are tied together and serve as SDA. The “SDA_{IN}” pin must be connected to act as SDA. The “SDA_{OUT}” pin may be disconnected. When “SDA_{OUT}” pin is disconnected, the acknowledgement signal will be ignored in the I²C-bus.

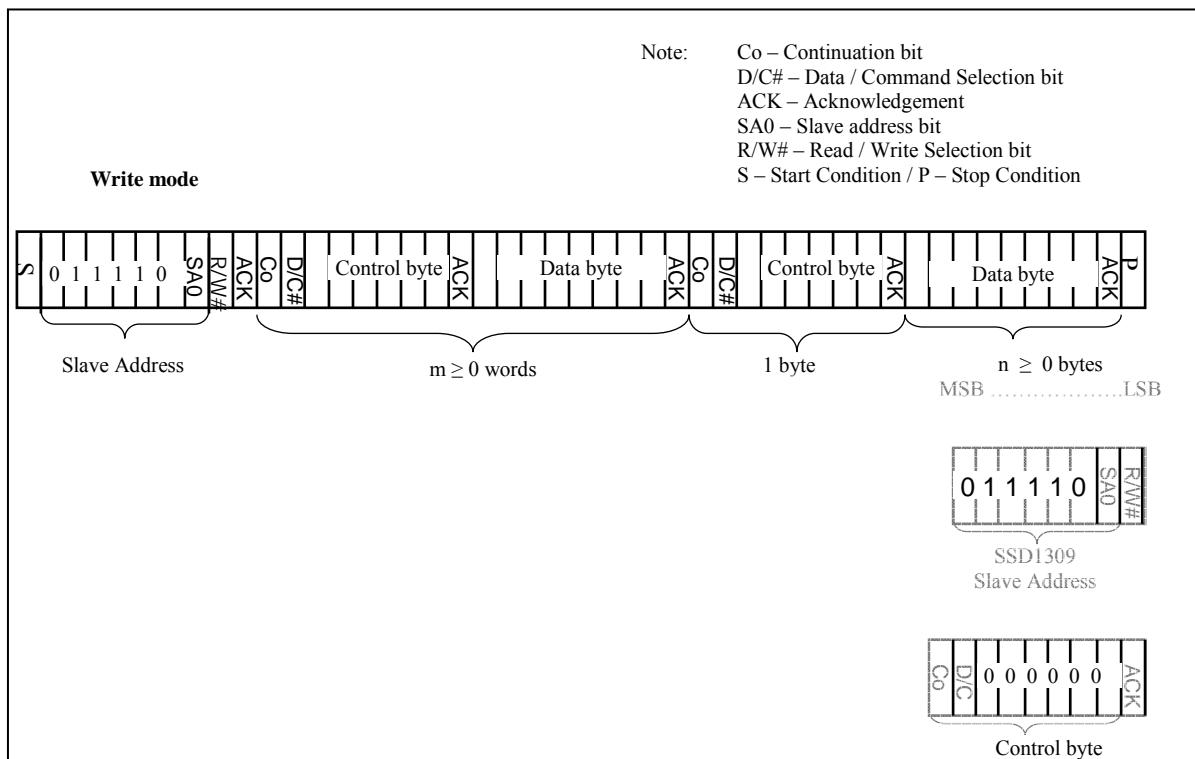
c) I²C-bus clock signal (SCL)

The transmission of information in the I²C-bus is following a clock signal, SCL. Each transmission of data bit is taken place during a single clock period of SCL.

8.1.5.1 I²C-bus Write data

The I²C-bus interface gives access to write data and command into the device. Please refer to Figure 8-7 for the write mode of I²C-bus in chronological order.

Figure 8-7 : I²C-bus data format



8.1.5.2 Write mode for I²C

- 1) The master device initiates the data communication by a start condition. The definition of the start condition is shown in Figure 8-8. The start condition is established by pulling the SDA from HIGH to LOW while the SCL stays HIGH.
- 2) The slave address is following the start condition for recognition use. For the SSD1309, the slave address is either “b0111100” or “b0111101” by changing the SA0 to LOW or HIGH (D/C pin acts as SA0).
- 3) The write mode is established by setting the R/W# bit to logic “0”.
- 4) An acknowledgement signal will be generated after receiving one byte of data, including the slave address and the R/W# bit. Please refer to the Figure 8-9 for the graphical representation of the acknowledge signal. The acknowledge bit is defined as the SDA line is pulled down during the HIGH period of the acknowledgement related clock pulse.
- 5) After the transmission of the slave address, either the control byte or the data byte may be sent across the SDA. A control byte mainly consists of Co and D/C# bits following by six “0” ‘s.
 - a. If the Co bit is set as logic “0”, the transmission of the following information will contain data bytes only.
 - b. The D/C# bit determines the next data byte is acted as a command or a data. If the D/C# bit is set to logic “0”, it defines the following data byte as a command. If the D/C# bit is set to logic “1”, it defines the following data byte as a data which will be stored at the GDDRAM. The GDDRAM column address pointer will be increased by one automatically after each data write.
- 6) Acknowledge bit will be generated after receiving each control byte or data byte.
- 7) The write mode will be finished when a stop condition is applied. The stop condition is also defined in Figure 8-8. The stop condition is established by pulling the “SDA in” from LOW to HIGH while the “SCL” stays HIGH.

Figure 8-8 : Definition of the Start and Stop Condition

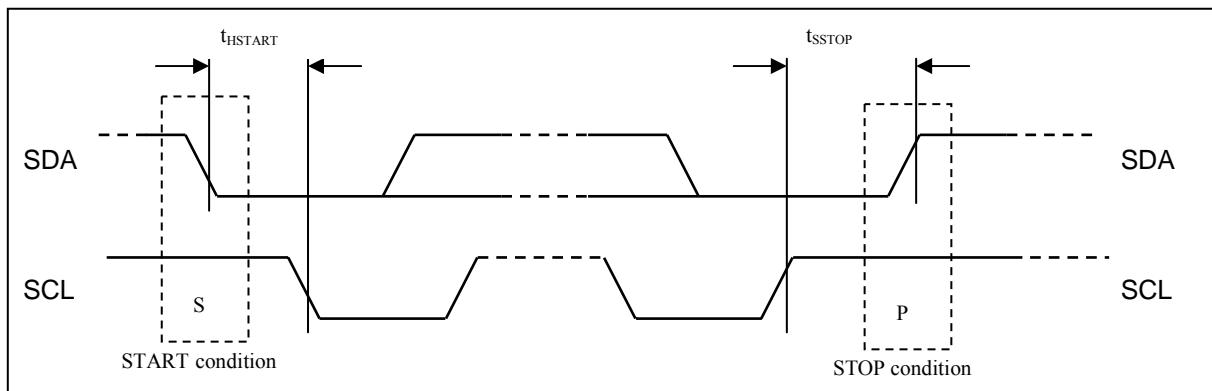
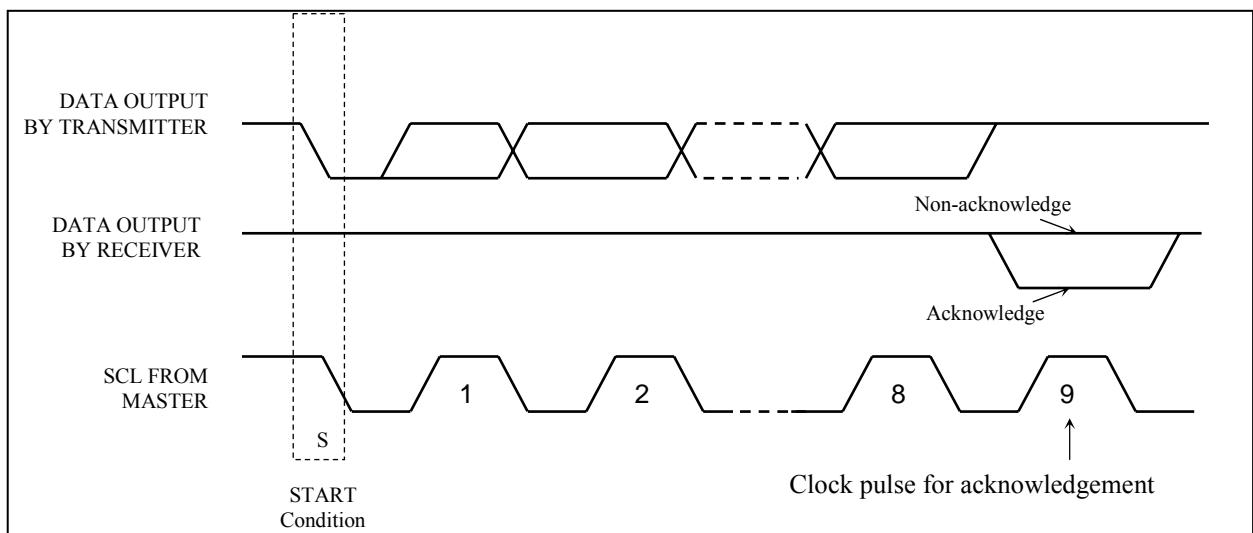


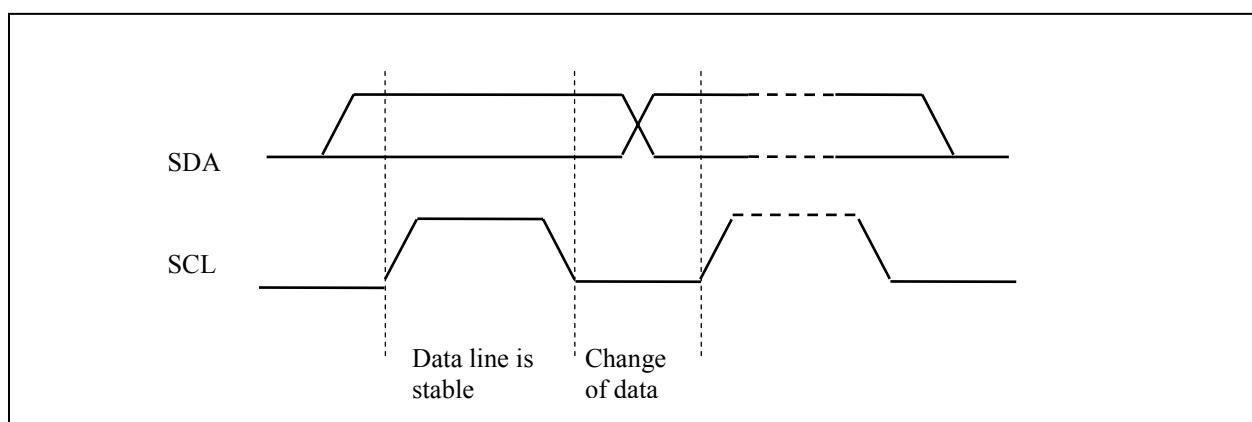
Figure 8-9 : Definition of the acknowledgement condition



Please be noted that the transmission of the data bit has some limitations.

1. The data bit, which is transmitted during each SCL pulse, must keep at a stable state within the “HIGH” period of the clock pulse. Please refer to the Figure 8-10 for graphical representations. Except in start or stop conditions, the data line can be switched only when the SCL is LOW.
2. Both the data line (SDA) and the clock line (SCL) should be pulled up by external resistors.

Figure 8-10 : Definition of the data transfer condition



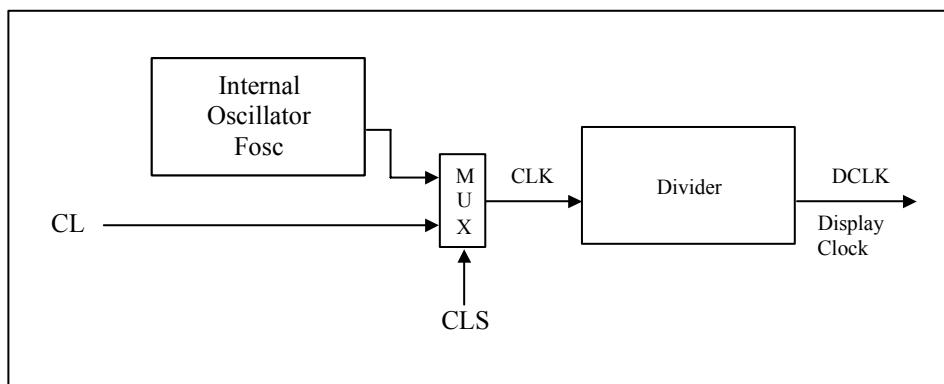
8.2 Command Decoder

This module determines whether the input data is interpreted as data or command. Data is interpreted based upon the input of the D/C# pin.

If D/C# pin is HIGH, D[7:0] is interpreted as display data written to Graphic Display Data RAM (GDDRAM). If it is LOW, the input at D[7:0] is interpreted as a command. Then data input will be decoded and written to the corresponding command register.

8.3 Oscillator Circuit and Display Time Generator

Figure 8-11 : Oscillator Circuit and Display Time Generator



This module is an on-chip LOW power RC oscillator circuitry. The operation clock (CLK) can be generated either from internal oscillator or external source CL pin. This selection is done by CLS pin. If CLS pin is pulled HIGH, internal oscillator is chosen and CL should be connected to V_{SS}. Pulling CLS pin LOW disables internal oscillator and external clock must be connected to CL pins for proper operation. When the internal oscillator is selected, its output frequency Fosc can be changed by command D5h A[7:4].

The display clock (DCLK) for the Display Timing Generator is derived from CLK. The division factor “D” can be programmed from 1 to 16 by command D5h

$$DCLK = F_{OSC} / D$$

The frame frequency of display is determined by the following formula.

$$F_{FRM} = \frac{F_{osc}}{D \times K \times \text{No. of Mux}}$$

where

- D stands for clock divide ratio. It is set by command D5h A[3:0]. The divide ratio has the range from 1 to 16.
- K is the number of display clocks per row. The value is derived by

$$K = \text{Phase 1 period} + \text{Phase 2 period} + K_o$$

$$= 2 + 2 + 65 = 69 \text{ at power on reset (that is } K_o \text{ is a constant that equals to 65)}$$

(Please refer to Section 8.5 “Segment Drivers / Common Drivers” for the details of the “Phase”)
- Number of multiplex ratio is set by command A8h. The power on reset value is 63 (i.e. 64MUX).
- Fosc is the oscillator frequency. It can be changed by command D5h A[7:4]. The higher the register setting results in higher frequency.

8.4 Reset Circuit

When RES# input is LOW, the chip is initialized with the following status:

1. Display is OFF
2. 128 x 64 Display Mode
3. Normal segment and display data column address and row address mapping (SEG0 mapped to address 00h and COM0 mapped to address 00h)
4. Shift register data clear in serial interface
5. Display start line is set at display RAM address 0
6. Column address counter is set at 0
7. Normal scan direction of the COM outputs
8. Contrast control register is set at 7Fh
9. Normal display mode (Equivalent to A4h command)

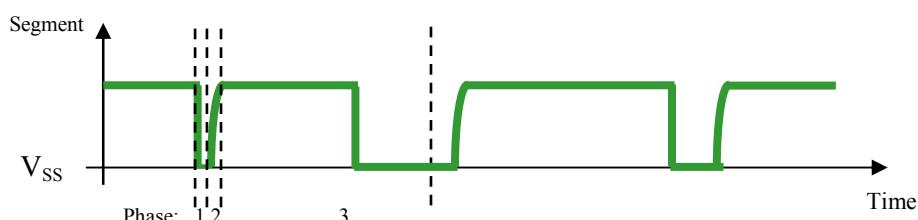
8.5 Segment Drivers / Common Drivers

Segment drivers deliver 128 current sources to drive the OLED panel. The driving current can be adjusted from 0 to 320 μ A with 256 steps. Common drivers generate voltage-scanning pulses.

The segment driving waveform is divided into three phases:

1. In phase 1, the OLED pixel charges of previous image are discharged in order to prepare for next image content display.
2. In phase 2, the OLED pixel is driven to the targeted voltage. The pixel is driven to attain the corresponding voltage level from V_{SS}. The period of phase 2 can be programmed in length from 1 to 15 DCLKs. If the capacitance value of the pixel of OLED panel is larger, a longer period is required to charge up the capacitor to reach the desired voltage.
3. In phase 3, the OLED driver switches to use current source to drive the OLED pixels and this is the current drive stage.

Figure 8-12 : Segment Output Waveform in three phases



After finishing phase 3, the driver IC will go back to phase 1 to display the next row image data. This three-step cycle is run continuously to refresh image display on OLED panel.

In phase 3, if the length of current drive pulse width is set to 65, after finishing 65 DCLKs in current drive phase, the driver IC will go back to phase 1 for next row display.

8.6 Graphic Display Data RAM (GDDRAM)

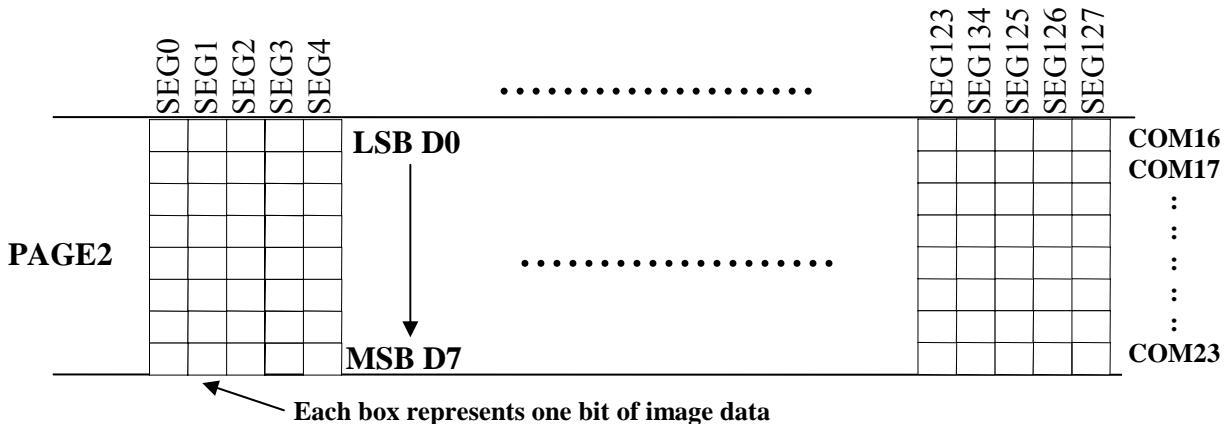
The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 128 x 64 bits and the RAM is divided into eight pages, from PAGE0 to PAGE7, which are used for monochrome 128x64 dot matrix display, as shown in Figure 8-13.

Figure 8-13 : GDDRAM pages structure of SSD1309

		Row re-mapping
PAGE0 (COM0-COM7)	Page 0	PAGE0 (COM 63-COM56)
PAGE1 (COM8-COM15)	Page 1	PAGE1 (COM 55-COM48)
PAGE2 (COM16-COM23)	Page 2	PAGE2 (COM47-COM40)
PAGE3 (COM24-COM31)	Page 3	PAGE3 (COM39-COM32)
PAGE4 (COM32-COM39)	Page 4	PAGE4 (COM31-COM24)
PAGE5 (COM40-COM47)	Page 5	PAGE5 (COM23-COM16)
PAGE6 (COM48-COM55)	Page 6	PAGE6 (COM15-COM8)
PAGE7 (COM56-COM63)	Page 7	PAGE7 (COM 7-COM0)
	SEG0 ----- SEG127	
Column re-mapping	SEG127 ----- SEG0	

When one data byte is written into GDDRAM, all the rows image data of the same page of the current column are filled (i.e. the whole column (8 bits) pointed by the column address pointer is filled.). Data bit D0 is written into the top row, while data bit D7 is written into bottom row as shown in Figure 8-14.

Figure 8-14 : Enlargement of GDDRAM (No row re-mapping and column-remapping)



For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software as shown in Figure 8-13.

For vertical shifting of the display, an internal register storing the display start line can be set to control the portion of the RAM data to be mapped to the display (command D3h).

8.7 SEG/COM Driving block

This block is used to derive the incoming power sources into the different levels of internal use voltage and current.

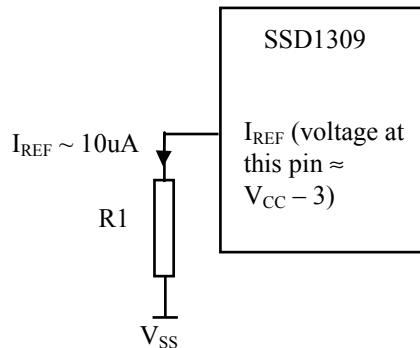
- V_{CC} is the most positive voltage supply.
- V_{COMH} is the Common deselected level. It is internally regulated.
- V_{LSS} is the ground path of the analog and panel current.
- I_{REF} is a reference current source for segment current drivers I_{SEG} . The relationship between reference current and segment current of a color is:

$$I_{SEG} = (\text{Contrast}+1) / 8 \times I_{REF}$$

in which the contrast (0~255) is set by Set Contrast command 81h

The magnitude of I_{REF} is controlled by the value of resistor, which is connected between I_{REF} pin and V_{SS} as shown in Figure 8-15. It is recommended to set I_{REF} to $10 \pm 2\mu A$ so as to achieve $I_{SEG} = 320\mu A$ at maximum contrast 255.

Figure 8-15 : I_{REF} Current Setting by Resistor Value



Since the voltage at I_{REF} pin is $V_{CC} - 3V$, the value of resistor $R1$ can be found as below:

For $I_{REF} = 10\mu A$, $V_{CC} = 12V$:

$$\begin{aligned} R1 &= (\text{Voltage at } I_{REF} - V_{SS}) / I_{REF} \\ &\approx (12 - 3) / 10\mu A \\ &= 900k\Omega \end{aligned}$$

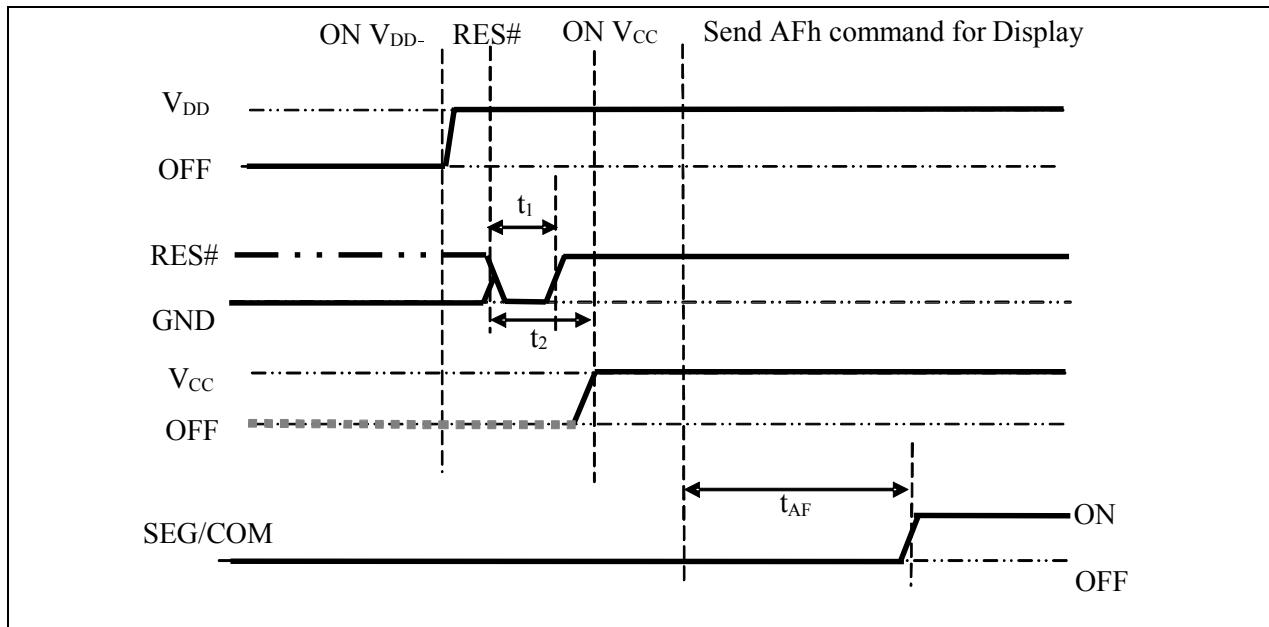
8.8 Power ON and OFF sequence

The following figures illustrate the recommended power ON and power OFF sequence of SSD1309

Power ON sequence:

1. Power ON V_{DD}
2. After V_{DD} become stable, set RES# pin LOW (logic low) for at least 3us (t_1) ⁽³⁾ and then HIGH (logic high).
3. After set RES# pin LOW (logic low), wait for at least 3us (t_2). Then Power ON V_{CC}⁽¹⁾
4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 100ms (t_{AF}).

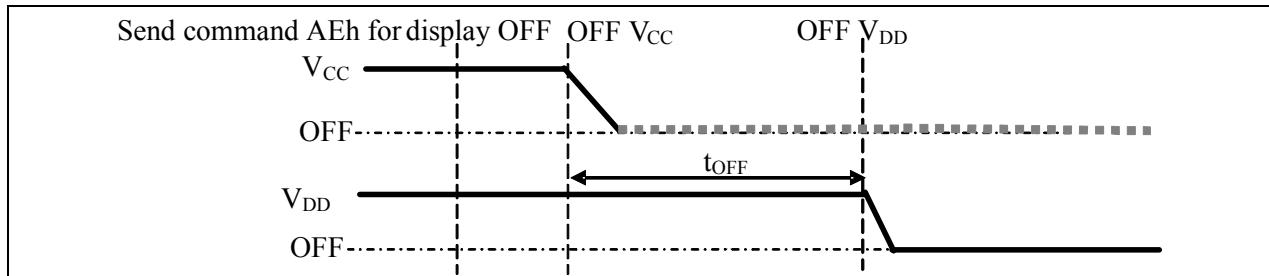
Figure 8-16 : The Power ON sequence



Power OFF sequence:

1. Send command AEh for display OFF.
2. Power OFF V_{CC}^{(1), (2)}
3. Power OFF V_{DD} after t_{OFF}⁽⁴⁾ (where Minimum t_{OFF}=0ms, typical t_{OFF}=100ms)

Figure 8-17 : The Power OFF sequence



Note:

- ⁽¹⁾ V_{CC} should be kept float (i.e. disable) when it is OFF.
- ⁽²⁾ Power Pins (V_{DD}, V_{CC}) can never be pulled to ground under any circumstance.
- ⁽³⁾ The register values are reset after t₁.
- ⁽⁴⁾ V_{DD} should not be Power OFF before V_{CC} Power OFF.

9 Command Table

(D/C#=0, R/W#(WR#) = 0, E(RD#=1) unless specific setting is stated)

9.1 Fundamental Command Table

Table 9-1: Fundamental Command Table

1. Fundamental Command Table											
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	81	1	0	0	0	0	0	0	1	Set Contrast Control	Double byte command to select 1 out of 256 contrast steps. Contrast increases as the value increases. (RESET = 7Fh)
0	A[7:0]	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		
0	A4/A5	1	0	1	0	0	1	0	X ₀	Entire Display ON	A4h, X ₀ =0b: Resume to RAM content display (RESET) Output follows RAM content A5h, X ₀ =1b: Entire display ON Output ignores RAM content
0	A6/A7	1	0	1	0	0	1	1	X ₀	Set Normal/Inverse Display	A6h, X[0]=0b: Normal display (RESET) 0 in RAM: OFF in display panel 1 in RAM: ON in display panel A7h, X[0]=1b: Inverse display 0 in RAM: ON in display panel 1 in RAM: OFF in display panel
0	AE/AF	1	0	1	0	1	1	1	X ₀	Set Display ON/OFF	AEh, X[0]=0b:Display OFF (sleep mode) (RESET) AFh X[0]=1b:Display ON in normal mode
0	E3	1	1	1	0	0	0	1	1	NOP	Command for no operation
0	FD	1	1	1	1	1	1	0	1	Set Command Lock	A[2]: MCU protection status. A[2] = 0b, Unlock OLED driver IC MCU interface from entering command (RESET) A[2] = 1b, Lock OLED driver IC MCU interface from entering command
0	A[2]	0	0	0	1	0	A ₂	1	0		Note (¹) The locked OLED driver IC MCU interface prohibits all commands and memory access except the FDh command

9.2 Scrolling Command Table

Table 9-2: Scrolling Command Table

2. Scrolling Command Table																				
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description									
0	26/27	0	0	1	0	0	1	1	X ₀	Continuous	26h, X[0]=0, Right Horizontal Scroll 27h, X[0]=1, Left Horizontal Scroll									
0	A[7:0]	0	0	0	0	0	0	0	0	Horizontal										
0	B[2:0]	*	*	*	*	*	B ₂	B ₁	B ₀	Scroll Setup										
0	C[2:0]	*	*	*	*	*	C ₂	C ₁	C ₀		A[7:0] : Dummy byte (Set as 00h)									
0	D[2:0]	*	*	*	*	*	D ₂	D ₁	D ₀		Horizontal scroll by 1 column									
0	E[7:0]	0	0	0	0	0	0	0	0											
0	F[7:0]	F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	F ₀											
0	G[7:0]	G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀		B[2:0] : Define start page address									
											<table border="1"> <tr><td>000b – PAGE0</td><td>011b – PAGE3</td><td>110b – PAGE6</td></tr> <tr><td>001b – PAGE1</td><td>100b – PAGE4</td><td>111b – PAGE7</td></tr> <tr><td>010b – PAGE2</td><td>101b – PAGE5</td><td></td></tr> </table>	000b – PAGE0	011b – PAGE3	110b – PAGE6	001b – PAGE1	100b – PAGE4	111b – PAGE7	010b – PAGE2	101b – PAGE5	
000b – PAGE0	011b – PAGE3	110b – PAGE6																		
001b – PAGE1	100b – PAGE4	111b – PAGE7																		
010b – PAGE2	101b – PAGE5																			
											C[2:0] : Set time interval between each scroll step in terms of frame frequency									
											<table border="1"> <tr><td>000b – 5 frames</td><td>100b – 2 frames</td></tr> <tr><td>001b – 64 frames</td><td>101b – 3 frames</td></tr> <tr><td>010b – 128 frames</td><td>110b – 4 frames</td></tr> <tr><td>011b – 256 frames</td><td>111b – 1 frames</td></tr> </table>	000b – 5 frames	100b – 2 frames	001b – 64 frames	101b – 3 frames	010b – 128 frames	110b – 4 frames	011b – 256 frames	111b – 1 frames	
000b – 5 frames	100b – 2 frames																			
001b – 64 frames	101b – 3 frames																			
010b – 128 frames	110b – 4 frames																			
011b – 256 frames	111b – 1 frames																			
											D[2:0] : Define end page address									
											<table border="1"> <tr><td>000b – PAGE0</td><td>011b – PAGE3</td><td>110b – PAGE6</td></tr> <tr><td>001b – PAGE1</td><td>100b – PAGE4</td><td>111b – PAGE7</td></tr> <tr><td>010b – PAGE2</td><td>101b – PAGE5</td><td></td></tr> </table>	000b – PAGE0	011b – PAGE3	110b – PAGE6	001b – PAGE1	100b – PAGE4	111b – PAGE7	010b – PAGE2	101b – PAGE5	
000b – PAGE0	011b – PAGE3	110b – PAGE6																		
001b – PAGE1	100b – PAGE4	111b – PAGE7																		
010b – PAGE2	101b – PAGE5																			
											E[7:0] : Dummy byte (Set as 00h)									
											F[7:0] : Define the start column (RESET = 00h)									
											G[7:0] : Define the end column address (RESET = 7Fh)									
											Notes:									
											(¹) The value of D[2:0] must be larger than or equal to B[2:0]									
											(²) The value of G[7:0] must be larger than or equal to F[7:0]									

2. Scrolling Command Table											
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	29/2A	0	0	1	0	1	0	X ₁	X ₀	Continuous Scroll	29h, X ₁ X ₀ =01b : Vertical and Right Horizontal Scroll
0	A[0]	*	*	*	*	*	*	*	A ₀	Vertical and Horizontal Scroll Setup	2Ah, X ₁ X ₀ =10b : Vertical and Left Horizontal Scroll
0	B[2:0]	*	*	*	*	*	B ₂	B ₁	B ₀		
0	C[2:0]	*	*	*	*	*	C ₂	C ₁	C ₀		
0	D[2:0]	*	*	*	*	*	D ₂	D ₁	D ₀		
0	E[5:0]	*	*	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀	A[0] : Set number of column scroll offset	0b No horizontal scroll 1b Horizontal scroll by 1 column
0	F[7:0]	F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	F ₀	B[2:0] : Define start page address	000b – PAGE0 011b – PAGE3 110b – PAGE6 001b – PAGE1 100b – PAGE4 111b – PAGE7 010b – PAGE2 101b – PAGE5
0	G[7:0]	G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀	C[2:0] : Set time interval between each scroll step in terms of frame frequency	000b – 5 frames 100b – 2 frames 001b – 64 frames 101b – 3 frames 010b – 128 frames 110b – 4 frames 011b – 256 frames 111b – 1 frames
										D[2:0] : Define end page address	000b – PAGE0 011b – PAGE3 110b – PAGE6 001b – PAGE1 100b – PAGE4 111b – PAGE7 010b – PAGE2 101b – PAGE5
										E[5:0] : Vertical scrolling offset e.g. E[5:0]=01h refer to offset =1 row E[5:0]=3Fh refer to offset =63 rows	
										F[7:0] : Define the start column (RESET = 00h)	
										G[7:0] : Define the end column address (RESET = 7Fh)	
										Note ⁽¹⁾ The value of D[2:0] must be larger than or equal to B[2:0]	
										⁽²⁾ The value of G[7:0] must be larger than or equal to F[7:0]	
0	2E	0	0	1	0	1	1	1	0	Deactivate scroll	Stop scrolling that is configured by command 26h/27h/29h/2Ah.
										Note ⁽¹⁾ After sending 2Eh command to deactivate the scrolling action, the ram data needs to be rewritten.	

2. Scrolling Command Table											
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	2F	0	0	1	0	1	1	1	1	Activate scroll	<p>Start scrolling that is configured by the scrolling setup commands :26h/27h/29h/2Ah with the following valid sequences:</p> <p>Valid command sequence 1: 26h; 2Fh. Valid command sequence 2: 27h; 2Fh. Valid command sequence 3: 29h; 2Fh. Valid command sequence 4: 2Ah; 2Fh.</p> <p>For example, if “26h; 2Ah; 2Fh.” commands are issued, the setting in the last scrolling setup command, i.e. 2Ah in this case, will be executed. In other words, setting in the last scrolling setup command overwrites the setting in the previous scrolling setup commands.</p>
0 0 0	A3 A[5:0] B[6:0]	1 * *	0 * B ₆	1 A ₅ B ₅	0 A ₄ B ₄	0 A ₃ B ₃	0 A ₂ B ₂	1 A ₁ B ₁	1 A ₀ B ₀	Set Vertical Scroll Area	<p>A[5:0] : Set No. of rows in top fixed area. The No. of rows in top fixed area is referenced to the top of the GDDRAM (i.e. row 0). [RESET = 0]</p> <p>B[6:0] : Set No. of rows in scroll area. This is the number of rows to be used for vertical scrolling. The scroll area starts in the first row below the top fixed area. [RESET = 64]</p> <p>Note</p> <ul style="list-style-type: none"> (1) A[5:0]+B[6:0] <= MUX ratio (2) B[6:0] <= MUX ratio (3a) Vertical scrolling offset (E[5:0] in 29h/2Ah) < B[6:0] (3b) Set Display Start Line (X₅X₄X₃X₂X₁X₀ of 40h~7Fh) < B[6:0] (4) The last row of the scroll area shifts to the first row of the scroll area. (5) For 64d MUX display <ul style="list-style-type: none"> A[5:0] = 0, B[6:0]=64 : whole area scrolls A[5:0]=0, B[6:0] < 64 : top area scrolls A[5:0] + B[6:0] < 64 : central area scrolls A[5:0] + B[6:0] = 64 : bottom area scrolls (6) When vertical scrolling is enabled by command 29h / 2Ah, the vertical scroll area is defined by this command

2. Scrolling Command Table																				
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description									
0	2C/2D	0	0	1	0	1	1	0	X ₀	Content Scroll	2Ch, X[0]=0, Right Horizontal Scroll by one column									
0	A[7:0]	0	0	0	0	0	0	0	0	Setup										
0	B[2:0]	*	*	*	*	*	B ₂	B ₁	B ₀		2Dh, X[0]=1, Left Horizontal Scroll by one column									
0	C[7:0]	0	0	0	0	0	0	0	1											
0	D[2:0]	*	*	*	*	*	D ₂	D ₁	D ₀		A[7:0] : Dummy byte (Set as 00h)									
0	E[7:0]	0	0	0	0	0	0	0	0		Horizontal scroll by 1 column									
0	F[7:0]	F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	F ₀											
0	G[7:0]	G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀		B[2:0] : Define start page address									
											<table border="1"> <tr><td>000b – PAGE0</td><td>011b – PAGE3</td><td>110b – PAGE6</td></tr> <tr><td>001b – PAGE1</td><td>100b – PAGE4</td><td>111b – PAGE7</td></tr> <tr><td>010b – PAGE2</td><td>101b – PAGE5</td><td></td></tr> </table>	000b – PAGE0	011b – PAGE3	110b – PAGE6	001b – PAGE1	100b – PAGE4	111b – PAGE7	010b – PAGE2	101b – PAGE5	
000b – PAGE0	011b – PAGE3	110b – PAGE6																		
001b – PAGE1	100b – PAGE4	111b – PAGE7																		
010b – PAGE2	101b – PAGE5																			
											C[7:0] : Dummy byte (Set as 01h)									
											D[2:0] : Define end page address									
											<table border="1"> <tr><td>000b – PAGE0</td><td>011b – PAGE3</td><td>110b – PAGE6</td></tr> <tr><td>001b – PAGE1</td><td>100b – PAGE4</td><td>111b – PAGE7</td></tr> <tr><td>010b – PAGE2</td><td>101b – PAGE5</td><td></td></tr> </table>	000b – PAGE0	011b – PAGE3	110b – PAGE6	001b – PAGE1	100b – PAGE4	111b – PAGE7	010b – PAGE2	101b – PAGE5	
000b – PAGE0	011b – PAGE3	110b – PAGE6																		
001b – PAGE1	100b – PAGE4	111b – PAGE7																		
010b – PAGE2	101b – PAGE5																			
											E[7:0] : Dummy byte (Set as 00h)									
											F[7:0] : Define the start column (RESET = 00h)									
											G[7:0] : Define the end column address (RESET = 7Fh)									
											Note									
											(¹) The value of D[2:0] must be larger than or equal to B[2:0]									
											(²) The value of G[7:0] must be larger than F[7:0]									
											(³) A delay time of <i>2/FrameFreq</i> must be set if sending the command of 2Ch / 2Dh consecutively.									

Note

(1) “*” stands for “Don’t care”.

9.3 Addressing Setting Command Table

Table 9-3: Addressing Setting Command Table

3. Addressing Setting Command Table											
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	00~0F	0	0	0	0	X ₃	X ₂	X ₁	X ₀	Set Lower Column Start Address for Page Addressing Mode	Set the lower nibble of the column start address register for Page Addressing Mode using X[3:0] as data bits. The initial display line register is reset to 0000b after RESET. Note ⁽¹⁾ This command is only for page addressing mode
0	10~1F	0	0	0	1	X ₃	X ₂	X ₁	X ₀	Set Higher Column Start Address for Page Addressing Mode	Set the higher nibble of the column start address register for Page Addressing Mode using X[3:0] as data bits. The initial display line register is reset to 0000b after RESET. Note ⁽¹⁾ This command is only for page addressing mode
0 0 A[1:0]	20 A[1:0]	0 * *	0 * *	1 * *	0 * *	0 * *	0 A ₁ A ₀	0 A ₁ A ₀	0 A ₀	Set Memory Addressing Mode	A[1:0] = 00b, Horizontal Addressing Mode A[1:0] = 01b, Vertical Addressing Mode A[1:0] = 10b, Page Addressing Mode (RESET) A[1:0] = 11b, Invalid
0 0 0	21 A[7:0] B[7:0]	0 A ₇ B ₇	0 A ₆ B ₆	1 A ₅ B ₅	0 A ₄ B ₄	0 A ₃ B ₃	0 A ₂ B ₂	0 A ₁ B ₁	1 A ₀ B ₀	Set Column Address	Setup column start and end address A[7:0] : Column start address, range : 0-127d, (RESET=0d) B[7:0]: Column end address, range : 0-127d, (RESET =127d) Note ⁽¹⁾ This command is only for horizontal or vertical addressing mode.
0 0 0	22 A[2:0] B[2:0]	0 * *	0 * *	1 * *	0 * *	0 * *	0 A ₂ B ₂	1 A ₁ B ₁	0 A ₀ B ₀	Set Page Address	Setup page start and end address A[2:0] : Page start Address, range : 0-7d, (RESET = 0d) B[2:0] : Page end Address, range : 0-7d, (RESET = 7d) Note ⁽¹⁾ This command is only for horizontal or vertical addressing mode.
0	B0~B7	1	0	1	1	0	X ₂	X ₁	X ₀	Set Page Start Address for Page Addressing Mode	Set GDDRAM Page Start Address (PAGE0~PAGE7) for Page Addressing Mode using X[2:0]. Note ⁽¹⁾ This command is only for page addressing mode

9.4 Hardware Configuration (Panel resolution & layout related) Command Table

Table 9-4: Hardware Configuration (Panel resolution & layout related) Command Table

4. Hardware Configuration (Panel resolution & layout related) Command Table											
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	40~7F	0	1	X ₅	X ₄	X ₃	X ₂	X ₁	X ₀	Set Display Start Line	Set display RAM display start line register from 0-63 using X ₅ X ₃ X ₂ X ₁ X ₀ . Display start line register is reset to 000000b during RESET.
0	A0/A1	1	0	1	0	0	0	0	X ₀	Set Segment Remap	A0h, X[0]=0b: column address 0 is mapped to SEG0 (RESET) A1h, X[0]=1b: column address 127 is mapped to SEG0
0 0	A8 A[5:0]	1 *	0 *	1 A ₅	0 A ₄	1 A ₃	0 A ₂	0 A ₁	0 A ₀	Set Multiplex Ratio	Set MUX ratio to N+1 MUX N=A[5:0] : from 16MUX to 64MUX, RESET= 111111b (i.e. 63d, 64MUX) A[5:0] from 0 to 14 are invalid entry.
0	C0/C8	1	1	0	0	X ₃	0	0	0	Set COM Output Scan Direction	C0h, X[3]=0b: normal mode (RESET) Scan from COM0 to COM[N-1] C8h, X[3]=1b: remapped mode. Scan from COM[N-1] to COM0 Where N is the Multiplex ratio.
0 0	D3 A[5:0]	1 *	1 *	0 A ₅	1 A ₄	0 A ₃	0 A ₂	1 A ₁	1 A ₀	Set Display Offset	Set vertical shift by COM from 0d~63d The value is reset to 00h after RESET.
0 0	DA A[5:4]	1 0	1 0	0 A ₅	1 A ₄	1 0	0 0	1 1	0 0	Set COM Pins Hardware Configuration	A[4]=0b, Sequential COM pin configuration A[4]=1b (RESET), Alternative COM pin configuration A[5]=0b (RESET), Disable COM Left/Right remap A[5]=1b, Enable COM Left/Right remap
0 0	DC A[1:0]	1 0	1 0	0 0	1 0	1 0	1 0	0 A ₁	0 A ₀	Set GPIO	A[1:0] GPIO : 00 pin HiZ, Input disabled 01 pin HiZ, Input enabled 10 pin output LOW [RESET] 11 pin output HIGH

9.5 Timing & Driving Scheme Setting Command Table

Table 9-5: Timing & Driving Scheme Setting Command Table

5. Timing & Driving Scheme Setting Command Table																																
0 0	D5 A[7:0]	1 A ₇	1 A ₆	0 A ₅	1 A ₄	0 A ₃	1 A ₂	0 A ₁	1 A ₀	Set Display Clock Divide Ratio/Oscillator Frequency																						
										A[3:0] : Define the divide ratio (D) of the display clocks (DCLK): Divide ratio= A[3:0] + 1, RESET is 0000b (divide ratio = 1) A[7:4] : Set the Oscillator Frequency, F _{Osc} . Oscillator Frequency increases with the value of A[7:4] and vice versa. RESET is 0111b Range:0000b~1111b Frequency increases as setting value increases.																						
0 0	D9 A[7:0]	1 A ₇	1 A ₆	0 A ₅	1 A ₄	1 A ₃	0 A ₂	0 A ₁	1 A ₀	Set Pre-charge Period																						
										A[3:0] : Phase 1 period of up to 15 DCLK Clock 0 is invalid entry (RESET=2h) A[7:4] : Phase 2 period of up to 15 DCLK Clock 0 is invalid entry (RESET=2h)																						
0 0	DB A[5:2]	1 0	1 0	0 A ₅	1 A ₄	1 A ₃	0 A ₂	1 0	1 0	Set V _{COMH} Deselect Level																						
										<table border="1"> <thead> <tr> <th>A[5:2]</th><th>Hex code</th><th>V_{COMH} deselect level</th></tr> </thead> <tbody> <tr> <td>0000b</td><td>00h</td><td>~ 0.64 x V_{CC}</td></tr> <tr> <td>1101b</td><td>34h</td><td>~ 0.78 x V_{CC} (RESET)</td></tr> <tr> <td>1111b</td><td>3Ch</td><td>~ 0.84 x V_{CC}</td></tr> </tbody> </table>											A[5:2]	Hex code	V _{COMH} deselect level	0000b	00h	~ 0.64 x V _{CC}	1101b	34h	~ 0.78 x V _{CC} (RESET)	1111b	3Ch	~ 0.84 x V _{CC}
A[5:2]	Hex code	V _{COMH} deselect level																														
0000b	00h	~ 0.64 x V _{CC}																														
1101b	34h	~ 0.78 x V _{CC} (RESET)																														
1111b	3Ch	~ 0.84 x V _{CC}																														

Note

(2) “*” stands for “Don’t care”.

Table 9-6 : Read Command Table

Bit Pattern	Command	Description
D ₇ D ₆ D ₅ D ₄ D ₃ D ₂ D ₁ D ₀	Status Register Read	D[7] : Reserved D[6] : "1" for display OFF / "0" for display ON D[5] : Reserved D[4] : Reserved D[3] : Reserved D[2] : Reserved D[1] : Reserved D[0] : Reserved

Note

⁽¹⁾ Patterns other than those given in the Command Table are prohibited to enter the chip as a command; as unexpected results can occur.

9.6 Data Read / Write

To read data from the GDDRAM, select HIGH for both the R/W# (WR#) pin and the D/C# pin for 6800-series parallel mode and select LOW for the E (RD#) pin and HIGH for the D/C# pin for 8080-series parallel mode. No data read is provided in serial mode operation.

In normal data read mode the GDDRAM column address pointer will be increased automatically by one after each data read.

Also, a dummy read is required before the first data read.

To write data to the GDDRAM, select LOW for the R/W# (WR#) pin and HIGH for the D/C# pin for both 6800-series parallel mode and 8080-series parallel mode. The serial interface mode is always in write mode. The GDDRAM column address pointer will be increased automatically by one after each data write.

Table 9-7 : Address increment table (Automatic)

D/C#	R/W# (WR#)	Comment	Address Increment
0	0	Write Command	No
0	1	Read Status	No
1	0	Write Data	Yes
1	1	Read Data	Yes

10 COMMAND DESCRIPTIONS

10.1 Set Lower Column Start Address for Page Addressing Mode (00h~0Fh)

This command specifies the lower nibble of the 8-bit column start address for the display data RAM under Page Addressing Mode. The column address will be incremented by each data access. Refer to Section 9.3 and Section 10.3 for details.

10.2 Set Higher Column Start Address for Page Addressing Mode (10h~1Fh)

This command specifies the higher nibble of the 8-bit column start address for the display data RAM under Page Addressing Mode. The column address will be incremented by each data access. Refer to Section 9.3 and Section 10.3 for details.

10.3 Set Memory Addressing Mode (20h)

There are 3 different memory addressing mode in SSD1309: page addressing mode, horizontal addressing mode and vertical addressing mode. This command sets the way of memory addressing into one of the above three modes. In there, “COL” means the graphic display data RAM column.

Page addressing mode (A[1:0]=10xb)

In page addressing mode, after the display RAM is read / written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and page address pointer is not changed. Users have to set the new page and column addresses in order to access the next page RAM content. The sequence of movement of the PAGE and column address point for page addressing mode is shown in Figure 10-1.

Figure 10-1 : Address Pointer Movement of Page addressing mode

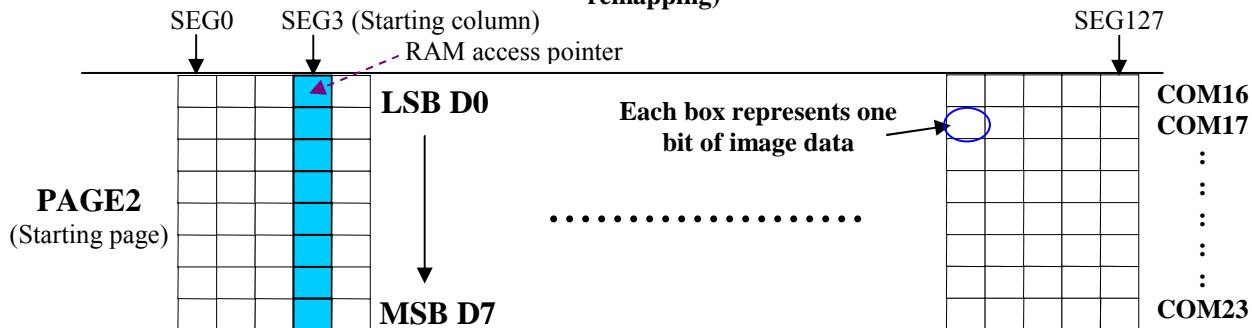
	COL0	COL 1	COL 126	COL 127
PAGE0	→	→	→	→	→
PAGE1	→	→	→	→	→
:	→	→	→	→	→
PAGE6	→	→	→	→	→
PAGE7	→	→	→	→	→

In normal display data RAM read or write and page addressing mode, the following steps are required to define the starting RAM access pointer location:

- Set the page start address of the target display location by command B0h to B7h.
- Set the lower start column address of pointer by command 00h~0Fh.
- Set the upper start column address of pointer by command 10h~1Fh.

For example, if the page address is set to B2h, lower column address is 03h and upper column address is 10h, then that means the starting column is SEG3 of PAGE2. The RAM access pointer is located as shown in Figure 10-2. The input data byte will be written into RAM position of column 3.

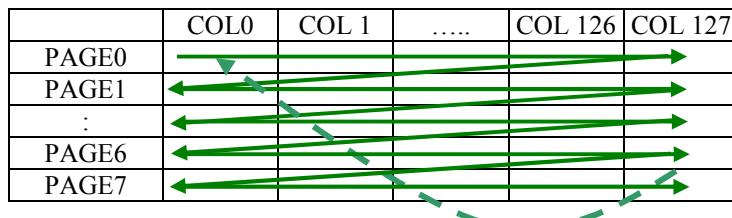
Figure 10-2 : Example of GDDRAM access pointer setting in Page Addressing Mode (No row and column-remapping)



Horizontal addressing mode (A[1:0]=00b)

In horizontal addressing mode, after the display RAM is read / written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and page address pointer is increased by 1. The sequence of movement of the page and column address point for horizontal addressing mode is shown in Figure 10-3. When both column and page address pointers reach the end address, the pointers are reset to column start address and page start address (Dotted line in Figure 10-3.)

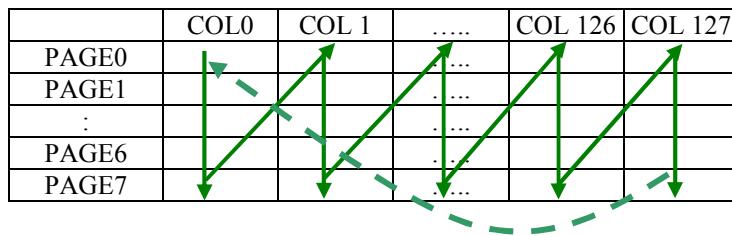
Figure 10-3 : Address Pointer Movement of Horizontal addressing mode



Vertical addressing mode: (A[1:0]=01b)

In vertical addressing mode, after the display RAM is read / written, the page address pointer is increased automatically by 1. If the page address pointer reaches the page end address, the page address pointer is reset to page start address and column address pointer is increased by 1. The sequence of movement of the page and column address point for vertical addressing mode is shown in Figure 10-4. When both column and page address pointers reach the end address, the pointers are reset to column start address and page start address (Dotted line in Figure 10-4.)

Figure 10-4 : Address Pointer Movement of Vertical addressing mode



In normal display data RAM read or write and horizontal / vertical addressing mode, the following steps are required to define the RAM access pointer location:

- Set the column start and end address of the target display location by command 21h.
- Set the page start and end address of the target display location by command 22h.

Example is shown in Figure 10-5.

10.4 Set Column Address (21h)

This triple byte command specifies column start address and end address of the display data RAM. This command also sets the column address pointer to column start address. This pointer is used to define the current read/write column address in graphic display data RAM. If horizontal address increment mode is enabled by command 20h, after finishing read/write one column data, it is incremented automatically to the next column address. Whenever the column address pointer finishes accessing the end column address, it is reset back to start column address and the row address is incremented to the next row.

10.5 Set Page Address (22h)

This triple byte command specifies page start address and end address of the display data RAM. This command also sets the page address pointer to page start address. This pointer is used to define the current read/write page address in graphic display data RAM. If vertical address increment mode is enabled by command 20h, after finishing read/write one page data, it is incremented automatically to the next page address. Whenever the page address pointer finishes accessing the end page address, it is reset back to start page address.

The figure below shows the way of column and page address pointer movement through the example: column start address is set to 2 and column end address is set to 97, page start address is set to 1 and page end address is set to 2; Horizontal address increment mode is enabled by command 20h. In this case, the graphic display data RAM column accessible range is from column 2 to column 97 and from page 1 to page 2 only. In addition, the column address pointer is set to 2 and page address pointer is set to 1. After finishing read/write one pixel of data, the column address is increased automatically by 1 to access the next RAM location for next read/write operation (*solid line in Figure 10-5*). Whenever the column address pointer finishes accessing the end column 97, it is reset back to column 2 and page address is automatically increased by 1 (*solid line in Figure 10-5*). While the end page 2 and end column 97 RAM location is accessed, the page address is reset back to 1 and the column address is reset back to 2 (*dotted line in Figure 10-5*).

Figure 10-5: Example of Column and Row Address Pointer Movement (LS pin pulled LOW)

	Col 0	Col 1	Col 2	Col 97	Col 98	Col 126	Col 127
PAGE0										
PAGE1										
PAGE2										
:										
PAGE6										
PAGE7										

10.6 Set Display Start Line (40h~7Fh)

This command sets the Display Start Line register to determine starting address of display RAM, by selecting a value from 0 to 63. With value equal to 0, RAM row 0 is mapped to COM0. With value equal to 1, RAM row 1 is mapped to COM0 and so on. Refer to Table 10-1 for more illustrations.

10.7 Set Contrast Control for BANK0 (81h)

This command sets the Contrast Setting of the display. The chip has 256 contrast steps from 00h to FFh. The segment output current increases as the contrast step value increases.

10.8 Set Segment Re-map (A0h/A1h)

This command changes the mapping between the display data column address and the segment driver. It allows flexibility in OLED module design. Refer to Section 9.4.

This command only affects subsequent data input. Data already stored in GDDRAM will have no changes.

10.9 Entire Display ON (A4h/A5h)

A4h command enable display outputs according to the GDDRAM contents.

If A5h command is issued, then by using A4h command, the display will resume to the GDDRAM contents. In other words, A4h command resumes the display from entire display “ON” stage.

A5h command forces the entire display to be “ON”, regardless of the contents of the display data RAM.

10.10 Set Normal/Inverse Display (A6h/A7h)

This command sets the display to be either normal or inverse. In normal display a RAM data of 1 indicates an “ON” pixel while in inverse display a RAM data of 0 indicates an “ON” pixel.

10.11 Set Multiplex Ratio (A8h)

This command switches the default 64 multiplex mode to any multiplex ratio, ranging from 16 to 64. The output pads COM0~COM63 will be switched to the corresponding COM signal.

10.12 Set Display ON/OFF (AEh/AFh)

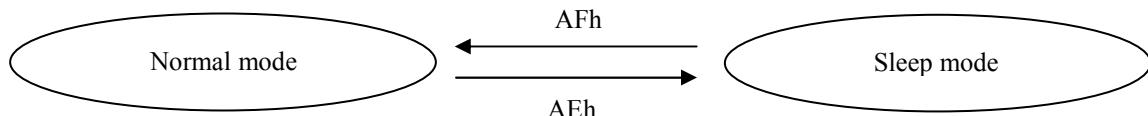
These single byte commands are used to turn the OLED panel display ON or OFF.

When the display is ON, the selected circuits by Set Master Configuration command will be turned ON.

When the display is OFF, those circuits will be turned OFF and the segment and common output are in V_{SS} state and high impedance state, respectively. These commands set the display to one of the two states:

- AEh : Display OFF
- AFh : Display ON

Figure 10-6 : Transition between different modes



10.13 Set Page Start Address for Page Addressing Mode (B0h~B7h)

This command positions the page start address from 0 to 7 in GDDRAM under Page Addressing Mode. Refer to Section 10.3 for details.

10.14 Set COM Output Scan Direction (C0h/C8h)

This command sets the scan direction of the COM output, allowing layout flexibility in the OLED module design. Additionally, the display will show once this command is issued. For example, if this command is sent during normal display then the graphic display will be vertically flipped immediately. Please refer to Table 10-3 for details.

10.15 Set Display Offset (D3h)

This is a double byte command. The second command specifies the mapping of the display start line to one of COM0~COM63 (assuming that COM0 is the display start line then the display start line register is equal to 0).

For example, to move the COM16 towards the COM0 direction by 16 lines the 6-bit data in the second byte should be given as 010000b. To move in the opposite direction by 16 lines the 6-bit data should be given by $64 - 16$, so the second byte would be 100000b. The following two tables (Table 10-1, Table 10-2) show the examples of setting the command C0h/C8h and D3h.

10.16 Set Display Clock Divide Ratio/ Oscillator Frequency (D5h)

This command consists of two functions:

- Display Clock Divide Ratio (D) (A[3:0])

Set the divide ratio to generate DCLK (Display Clock) from CLK. The divide ratio is from 1 to 16, with reset value = 0000b. Please refer to section 8.3 for the details relationship of DCLK and CLK.

- Oscillator Frequency (A[7:4])

Program the oscillator frequency Fosc that is the source of CLK if CLS pin is pulled high. The 4-bit value results in 16 different frequency settings available as shown below. The default setting is 1000b.

10.17 Set Pre-charge Period (D9h)

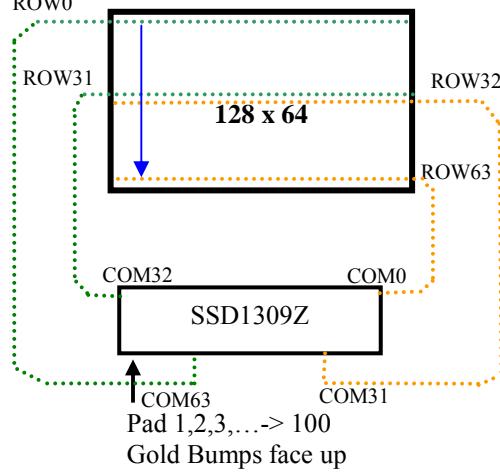
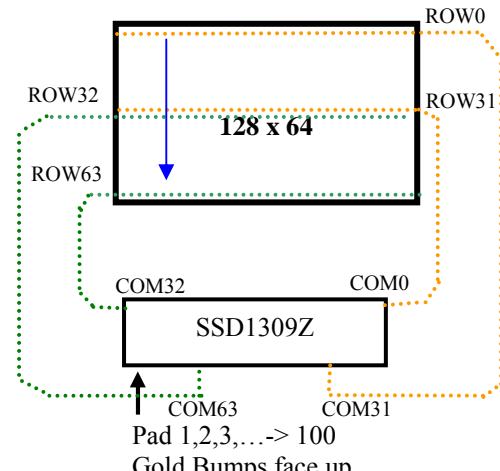
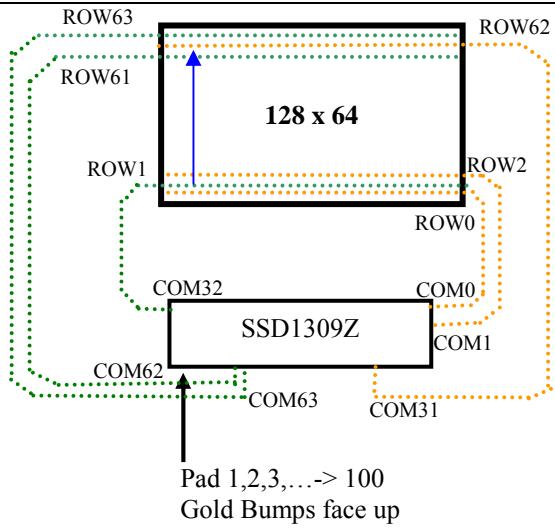
This command is used to set the duration of the pre-charge period. The interval is counted in number of DCLK, where RESET equals to 2 DCLKs.

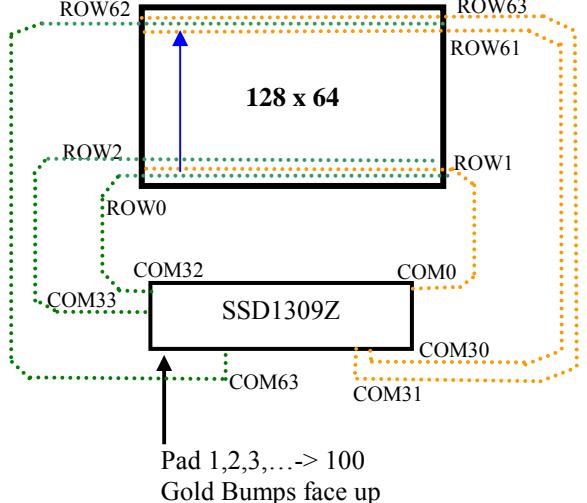
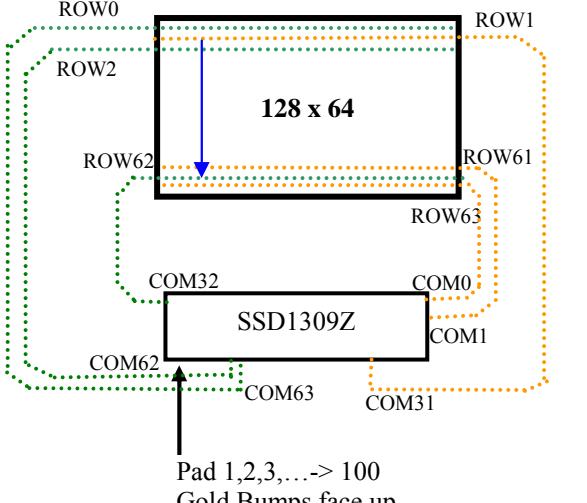
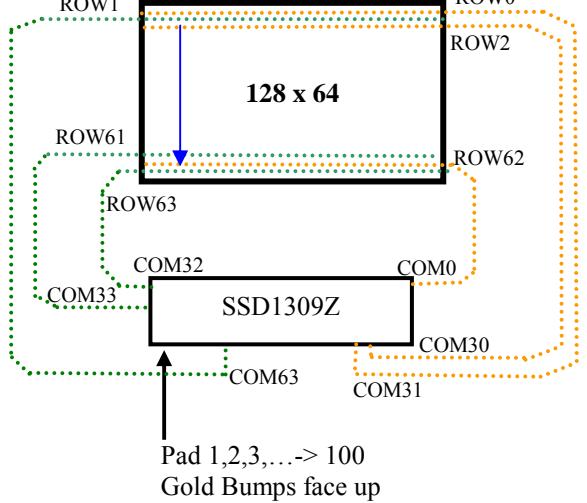
10.18 Set COM Pins Hardware Configuration (DAh)

This command sets the COM signals pin configuration to match the OLED panel hardware layout. The table below shows the COM pin configuration under different conditions (for MUX ratio =64):

Table 10-3 : COM Pins Hardware Configuration

Conditions	COM pins Configurations
1 Sequential COM pin configuration (DAh A[4] =0) COM output Scan direction: from COM0 to COM63 (C0h) Disable COM Left/Right remap (DAh A[5] =0)	
2 Sequential COM pin configuration (DAh A[4] =0) COM output Scan direction: from COM0 to COM63 (C0h) Enable COM Left/Right remap (DAh A[5] =1)	

Conditions	COM pins Configurations
3 Sequential COM pin configuration (DAh A[4] =0) COM output Scan direction: from COM63 to COM0 (C8h) Disable COM Left/Right remap (DAh A[5] =0)	 <p>ROW0 ROW31 128 x 64 ROW32 ROW63 COM32 COM0 COM63 COM31 Pad 1,2,3,...> 100 Gold Bumps face up</p>
4 Sequential COM pin configuration (DAh A[4] =0) COM output Scan direction: from COM63 to COM0 (C8h) Enable COM Left/Right remap (DAh A[5] =1)	 <p>ROW0 ROW32 ROW63 128 x 64 ROW31 COM32 COM0 COM63 COM31 Pad 1,2,3,...> 100 Gold Bumps face up</p>
5 Alternative COM pin configuration (DAh A[4] =1) COM output Scan direction: from COM0 to COM63 (C0h) Disable COM Left/Right remap (DAh A[5] =0)	 <p>ROW63 ROW61 ROW1 128 x 64 ROW0 ROW2 COM32 COM0 COM1 COM62 COM63 COM31 Pad 1,2,3,...> 100 Gold Bumps face up</p>

Conditions	COM pins Configurations
6 Alternative COM pin configuration (DAh A[4]=1) COM output Scan direction: from COM0 to COM63 (C0h) Enable COM Left/Right remap (DAh A[5]=1)	 <p>128 x 64</p> <p>SSD1309Z</p> <p>Pad 1,2,3,...> 100 Gold Bumps face up</p>
7 Alternative COM pin configuration (DAh A[4]=1) COM output Scan direction: from COM63 to COM0(C8h) Disable COM Left/Right remap (DAh A[5]=0)	 <p>128 x 64</p> <p>SSD1309Z</p> <p>Pad 1,2,3,...> 100 Gold Bumps face up</p>
8 Alternative COM pin configuration (DAh A[4]=1) COM output Scan direction: from COM63 to COM0(C8h) Enable COM Left/Right remap (DAh A[5]=1)	 <p>128 x 64</p> <p>SSD1309Z</p> <p>Pad 1,2,3,...> 100 Gold Bumps face up</p>

10.19 Set V_{COMH} Deselect Level (DBh)

This command adjusts the V_{COMH} regulator output.

10.20 Set GPIO (DCh)

This double byte command is used to set the state of GPIO pin. Refer to Table 9-4 for details.

10.21 NOP (E3h)

No Operation Command.

10.22 Set Command Lock (FDh)

This double byte command is used to lock the OLED driver IC from accepting any command except itself. After entering FDh 16h (A[2]=1b), the OLED driver IC will not respond to any newly-entered command (except FDh 12h A[2]=0b) and there will be no memory access. This is called “Lock” state. That means the OLED driver IC ignore all the commands (except FDh 12h A[2]=0b) during the “Lock” state.

Entering FDh 12h (A[2]=0b) can unlock the OLED driver IC. That means the driver IC resumes from the “Lock” state, and the driver IC will then respond to the command and memory access.

10.23 Horizontal Scroll Setup (26h/27h)

This command consists of seven consecutive bytes to set up the horizontal scroll parameters and determines the scrolling start page, end page, scrolling speed, start column and end column; refer to Table 9-2 for details.

Before issuing this command the horizontal scroll must be deactivated (2Eh). Otherwise, RAM content may be corrupted.

The SSD1309 horizontal scroll is designed for 128 columns scrolling. The following two figures (Figure 10-7, Figure 10-8, and Figure 10-9) show the examples of using the horizontal scroll:

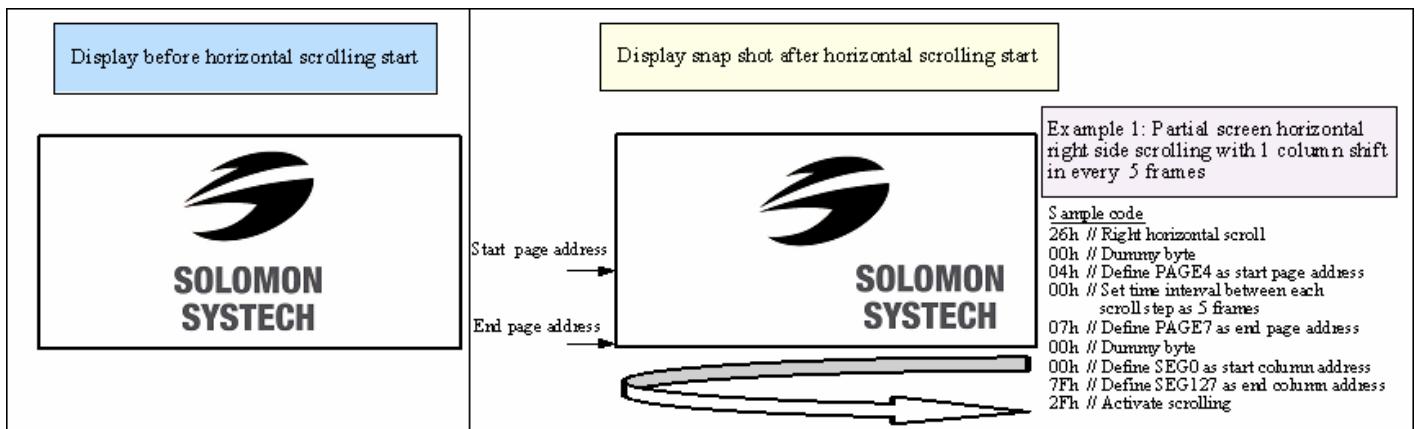
Figure 10-7: Horizontal scroll example: Scroll RIGHT by 1 column

Original Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	SEG122	SEG123	SEG124	SEG125	SEG126	SEG127
After one scroll step	SEG127	SEG0	SEG1	SEG2	SEG3	SEG4	SEG121	SEG122	SEG123	SEG124	SEG125	SEG126

Figure 10-8: Horizontal scroll example: Scroll LEFT by 1 column

Original Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	SEG122	SEG123	SEG124	SEG125	SEG126	SEG127	SEG0
After one scroll step	SEG1	SEG2	SEG3	SEG4	SEG5	SEG6	SEG123	SEG124	SEG125	SEG126	SEG127	SEG0	SEG127

Figure 10-9: Horizontal scrolling setup example (LS pin pull LOW)



10.24 Continuous Vertical and Horizontal Scroll Setup (29h/2Ah)

This command consists of seven consecutive bytes to set up the continuous vertical scroll parameters and determine the scrolling start page, end page, scrolling speed and vertical scrolling offset; refer to Table 9-2 for details.

If the vertical scrolling offset byte E[5:0] of command 29h / 2Ah is set to zero, then only horizontal scrolling is performed (like command 26/27h). On the other hand, if the number of column scroll offset byte A[0] is set to zero, then only vertical scrolling is performed.

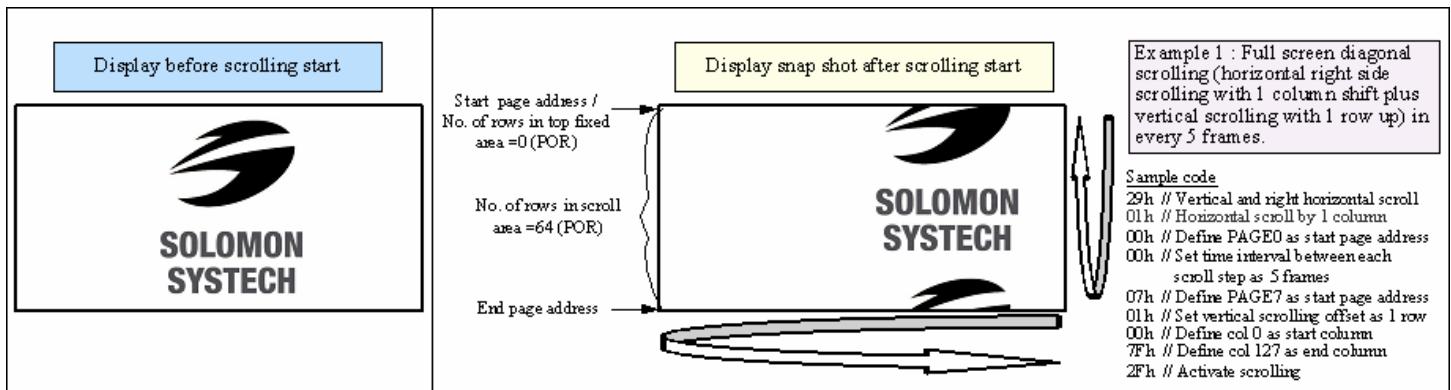
Continuous diagonal (horizontal + vertical) scrolling would be enabled if both A[0] and E[5:0] are set to be non-zero, whereas full column diagonal scrolling mode is suggested by setting F[7:0]=00h and G[7:0]=7Fh.

Before issuing this command the scroll must be deactivated (2Eh), or otherwise, RAM content may be corrupted. The following figures (Figure 10-10 and Figure 10-11) show the examples of using the continuous vertical scroll and the continuous diagonal scroll, respectively.

Figure 10-10: Continuous Vertical scrolling setup example (LS pin pull LOW)

Display before vertical scrolling start	Display snap shot after vertical scrolling start
	 <div data-bbox="1150 332 1499 415"> <p>Example 1 : Full screen vertical scrolling with 1 row up in every 5 frames</p> </div> <div data-bbox="1150 415 1483 640"> <p>Sample code</p> <pre>29h // Vertical and right horizontal scroll 00h // No horizontal scroll 00h // Dummy byte for start page address 00h // Set time interval between each scroll step as 5 frames 00h // Dummy byte for end page address 01h // Set vertical scrolling offset as 1 row 00h // Define col 0 as start column 7Fh // Define col 127 as end column 2Fh // Activate scrolling</pre> </div>
	 <div data-bbox="1150 669 1499 752"> <p>Example 2 : Partial screen (top area) vertical scrolling with 1 row up in every 64 frames</p> </div> <div data-bbox="1150 752 1483 1037"> <p>Sample code</p> <pre>A3h // Set Vertical Scroll Area 00h // Set 0 row in top fixed area 28h // Set 40 rows in scroll area 29h // Vertical and right horizontal scroll 00h // No horizontal scroll 00h // Dummy byte for start page address 01h // Set time interval between each scroll step as 64 frames 00h // Dummy byte for end page address 01h // Set vertical scrolling offset as 1 row 00h // Define col 0 as start column 7Fh // Define col 127 as end column 2Fh // Activate scrolling</pre> </div>

Figure 10-11: Continuous Vertical and Horizontal scrolling setup example (LS pin pull LOW)



10.25 Deactivate Scroll (2Eh)

This command stops the motion of scrolling. After sending 2Eh command to deactivate the scrolling action, the ram data needs to be rewritten.

10.26 Activate Scroll (2Fh)

This command starts the motion of scrolling and should only be issued after the scroll setup parameters have been defined by the scrolling setup commands: 26h / 27h / 29h / 2Ah. The setting in the latest scrolling setup command overwrites the setting in the previous scrolling setup command.

The following actions are prohibited after the scrolling is activated

1. RAM access (Data write or read)
2. Changing the horizontal scroll setup parameters

10.27 Set Vertical Scroll Area (A3h)

This command consists of 3 consecutive bytes to set up the vertical scroll area. For the continuous vertical scroll function (command 29h / 2Ah), the number of rows in the vertical scroll area can be set smaller than or equating to the MUX ratio. Figure 10-10 shows a vertical scrolling example with different settings in vertical scroll area.

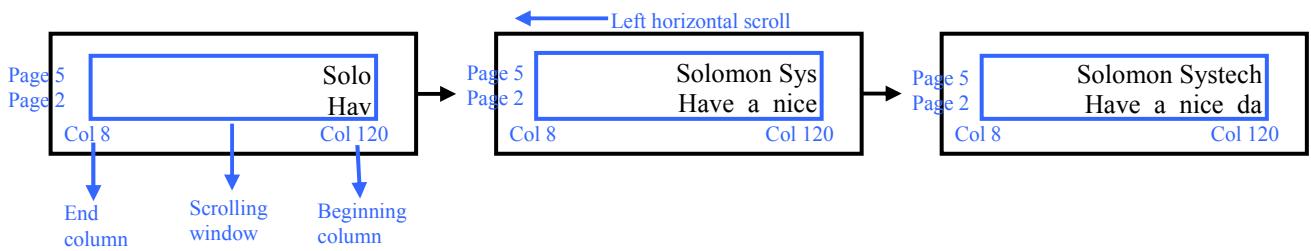
10.28 Content Scroll Setup (2Ch/2Dh)

This command consists of seven consecutive bytes to set up the horizontal scroll parameters and determine the scrolling start page, end page, start column and end column. One column will be scrolled horizontally by sending the setting of command 2Ch / 2Dh once.

When command 2Ch / 2Dh are sent consecutively, a delay time of $\frac{2}{FrameFreq}$ must be set.

Figure 10-12 shown an example of using 2Dh “Content Scroll Setup” command for horizontal scrolling to left with infinite content update. In there, “Col” means the graphic display data RAM column.

Figure 10-12: Content Scrolling example (2Dh, Left Horizontal Scroll by one column)



By using command 2Ch/2Dh, RAM contents are scrolled and updated by one column. Table 10-4 is an example of content scrolling setting of SSD1309 (scrolling window of 4 pages). The values of registers depend on different conditions and applications.

Table 10-4 : Content Scrolling software flow example (Page addressing mode – command 20h, 02h)

Step	Action	D/C#	Code	Remarks
1	For i= 1 to n	-	-	Create “For loop” for infinite content scrolling
2	Set Content scrolling command (scrolling window : Page 2 to 5, Col 8 to Col 120)	0	2Dh	Left Horizontal Scroll by one column
		0	00h	A[7:0] : Dummy byte (Set as 00h)
		0	02h	B[2:0] : Define start page address
		0	01h	C[7:0] : Dummy byte (Set as 01h)
		0	05h	D[2:0] : Define end page address
		0	00h	E[7:0] : Dummy byte (Set as 00h)
		0	08h	F[6:0] : Define start column address
		0	78h	G[6:0] : Define end column address
3	Add Delay time of $2/FrameFreq$	-	-	E.g. Delay 20ms if frame freq \approx 100Hz
4	Write RAM on the beginning column of the scrolling window			
	Write RAM on (Page2, Col 120) <i>(Content update in beginning column)</i>	0	B2h	Set Page Start Address for Page Addressing Mode
		0	17h	Set Higher Column Start Address for Page Addressing Mode
		0	08h	Set Lower Column Start Address for Page Addressing Mode
		1	-	Write data to fill the RAM
	Write RAM on (Page3, Col 120) <i>(Content update in beginning column)</i>	0	B3h	Set Page Start Address for Page Addressing Mode
		0	17h	Set Higher Column Start Address for Page Addressing Mode
		0	08h	Set Lower Column Start Address for Page Addressing Mode
		1	-	Write data to fill the RAM
	Write RAM on (Page4, Col 120) <i>(Content update in beginning column)</i>	0	B4h	Set Page Start Address for Page Addressing Mode
		0	17h	Set Higher Column Start Address for Page Addressing Mode
		0	08h	Set Lower Column Start Address for Page Addressing Mode
		1	-	Write data to fill the RAM
	Write RAM on (Page5, Col 120) <i>(Content update in beginning column)</i>	0	B5h	Set Page Start Address for Page Addressing Mode
		0	17h	Set Higher Column Start Address for Page Addressing Mode
		0	08h	Set Lower Column Start Address for Page Addressing Mode
		1	-	Write data to fill the RAM
5	i=i+1	-	-	Go to next “For loop”
	Delay timing	-	-	Set time interval between each scroll step if necessary
	End			

There are 3 different memory addressing mode in SSD1309: page addressing mode, horizontal addressing mode and vertical addressing mode and it is selected by command 20h. Table 10-4 is an example of content scrolling software flow under page addressing mode, while vertical addressing mode example is shown in below Table 10-5.

Table 10-5 : Content Scrolling setting example (Vertical addressing mode – command 20h, 01h)

Step	Action	D/C#	Code	Remarks
1	For i= 1 to n	-	-	Create “For loop” for infinite content scrolling
2	Set Content scrolling command (scrolling window : Page 2 to 5, Col 8 to Col 120)	0	2Dh	Left Horizontal Scroll by one column
		0	00h	A[7:0] : Dummy byte (Set as 00h)
		0	02h	B[2:0] : Define start page address
		0	01h	C[7:0] : Dummy byte (Set as 01h)
		0	05h	D[2:0] : Define end page address
		0	00h	E[7:0] : Dummy byte (Set as 00h)
		0	08h	F[6:0] : Define start column address
		0	78h	G[6:0] : Define end column address
3	Add Delay time of $2/FrameFreq$	-	-	E.g. Delay 20ms if frame freq \approx 100Hz
4	Write RAM on the beginning column of the scrolling window (Page 2 to 5, Col 120) <i>(Content update in beginning column)</i>	0	21h	Set Column address
		0	78h	Set column start address for Vertical Addressing Mode
		0	78h	Set column end address for Vertical Addressing Mode
		0	22h	Set Page address
		0	02h	Set start page address for Vertical Addressing Mode
		0	05h	Set end page address for Vertical Addressing Mode
		1	-	Write data to fill the RAM
5	i=i+1	-	-	Go to next “For loop”
	Delay timing	-	-	Set time interval between each scroll step if necessary
	End			

11 MAXIMUM RATINGS

Table 11-1 : Maximum Ratings (Voltage Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V _{DD}	Supply Voltage	-0.3 to +4	V
V _{CC}		0 to 17	V
V _{SEG}	SEG output voltage	0 to V _{CC}	V
V _{COM}	COM output voltage	0 to 0.9*V _{CC}	V
V _{in}	Input voltage	V _{SS} -0.3 to V _{DD} +0.3	V
T _A	Operating Temperature	-40 to +85	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C

Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description section.

This device may be light sensitive. Caution should be taken to avoid exposure of this device to any light source during normal operation. This device is not radiation protected.

12 DC CHARACTERISTICS

Condition (Unless otherwise specified):

Voltage referenced to V_{SS}, V_{DD} = 1.65 V to 3.3V, T_A = 25°C

Table 12-1 : DC Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V _{CC}	Operating Voltage	-	7	-	16	V
V _{DD}	Logic Supply Voltage	-	1.65	-	3.3	V
V _{OH}	High Logic Output Level	I _{OUT} = 100uA, 3.3MHz	0.9 x V _{DD}	-	-	V
V _{OL}	Low Logic Output Level	I _{OUT} = 100uA, 3.3MHz	-	-	0.1 x V _{DD}	V
V _{IH}	High Logic Input Level	-	0.8 x V _{DD}	-	-	V
V _{IL}	Low Logic Input Level	-	-	-	0.2 x V _{DD}	V
I _{DD,SLEEP}	Sleep mode Current	V _{DD} = 1.65V~3.3V, V _{CC} = 7V~16V Display OFF, No panel attached	-	-	10	uA
I _{CC,SLEEP}	Sleep mode Current	V _{DD} = 1.65V~3.3V, V _{CC} = 7V~16V Display OFF, No panel attached	-	-	10	uA
I _{CC}	V _{CC} Supply Current V _{DD} = 2.8V, V _{CC} = 12, I _{REF} = 10uA, No loading, Display ON, All ON	Contrast = FFh	-	450	580	uA
I _{DD}	V _{DD} Supply Current V _{DD} = 2.8V, V _{CC} = 12, I _{REF} = 10uA , No loading, Display ON, All ON,		-	90	110	uA
I _{SEG}	Segment Output Current, V _{DD} = 2.8V, V _{CC} =12V, I _{REF} =10uA, Display ON.	Contrast=FFh	280	310	340	uA
		Contrast=AFh	-	215	-	
		Contrast=7Fh	-	155	-	
		Contrast=3Fh	-	78	-	
		Contrast=0Fh	-	20	-	
Dev	Segment output current uniformity	Dev = (I _{SEG} - I _{MID})/I _{MID} I _{MID} = (I _{MAX} + I _{MIN})/2 I _{SEG[0:127]} = Segment current at contrast setting = FFh	-3	-	3	%
Adj. Dev	Adjacent pin output current uniformity (contrast setting = FFh)	Adj Dev = (I[n]-I[n+1]) / (I[n]+I[n+1])	-2	-	2	%

13 AC CHARACTERISTICS

Conditions:

Voltage referenced to V_{SS}

V_{DD}=1.65 to 3.3V

T_A = 25°C

Table 13-1 : AC Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
Fosc ⁽¹⁾	Oscillation Frequency of Display Timing Generator	V _{DD} = 2.8V	360	450	540	kHz
F _{FRM}	Frame Frequency	128x64 Graphic Display Mode, Display ON, Internal Oscillator Enabled	-	F _{osc} x 1/(D _x K _x 64) ⁽²⁾	-	Hz
RES#	Reset low pulse width		3	-	-	us

Note

⁽¹⁾ Fosc stands for the frequency value of the internal oscillator and the value is measured when command D5h A[7:4] is in default value.

⁽²⁾ D: divide ratio (default value = 1)

K: number of display clocks per row period (default value = 69)

Please refer to 9.5 (Set Display Clock Divide Ratio/Oscillator Frequency, D5h) for detailed description

Table 13-2 : 6800-Series MCU Parallel Interface Timing Characteristics

($V_{DD} - V_{SS} = 1.65V$ to $3.3V$, $T_A = 25^\circ C$)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	20	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DW}	Data Write Time	80	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	20	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW_{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns

Figure 13-1 : 6800-series MCU parallel interface characteristics

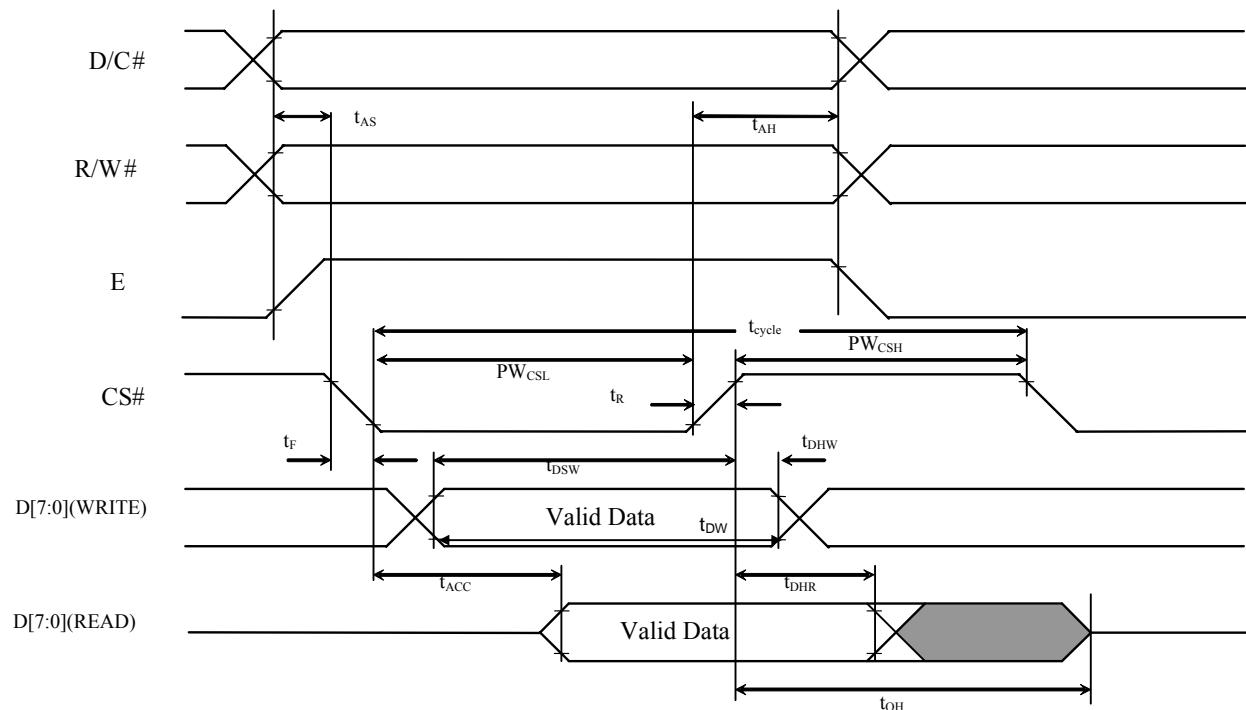


Table 13-3 : 8080-Series MCU Parallel Interface Timing Characteristics

($V_{DD} - V_{SS} = 1.65V \sim 3.3V$, $T_A = 25^\circ C$)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	20	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DW}	Data Write Time	70	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
t_{PWLR}	Read Low Time	120	-	-	ns
t_{PWLW}	Write Low Time	60	-	-	ns
t_{PWHR}	Read High Time	60	-	-	ns
t_{PWHW}	Write High Time	60	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns
t_{CS}	Chip select setup time	0	-	-	ns
t_{CSH}	Chip select hold time to read signal	0	-	-	ns
t_{CSF}	Chip select hold time	20	-	-	ns

Figure 13-2 : 8080-series parallel interface characteristics

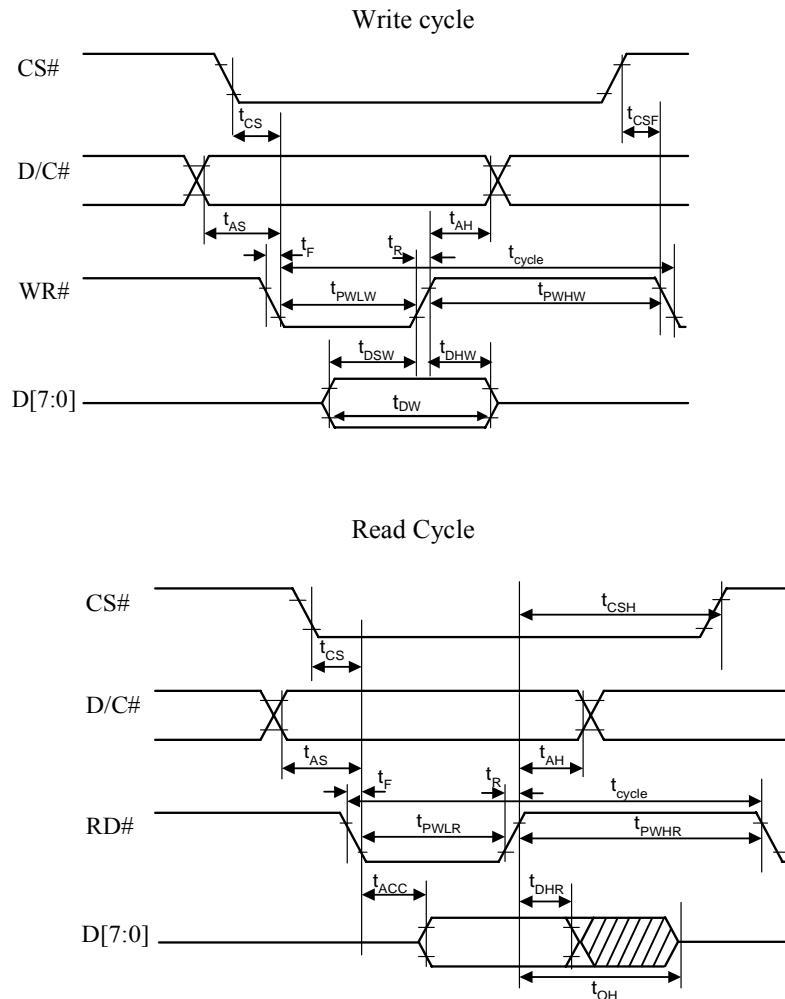


Table 13-4 : Serial Interface Timing Characteristics (4-wire SPI)

($V_{DD} - V_{SS} = 1.65V \sim 3.3V$, $T_A = 25^\circ C$)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	100	-	-	ns
t_{AS}	Address Setup Time	15	-	-	ns
t_{AH}	Address Hold Time	15	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	50	-	-	ns
t_{DW}	Data Write Time	55	-	-	ns
t_{DSW}	Write Data Setup Time	15	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{CLKL}	Clock Low Time	50	-	-	ns
t_{CLKH}	Clock High Time	50	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns

Figure 13-3 : Serial interface characteristics (4-wire SPI)

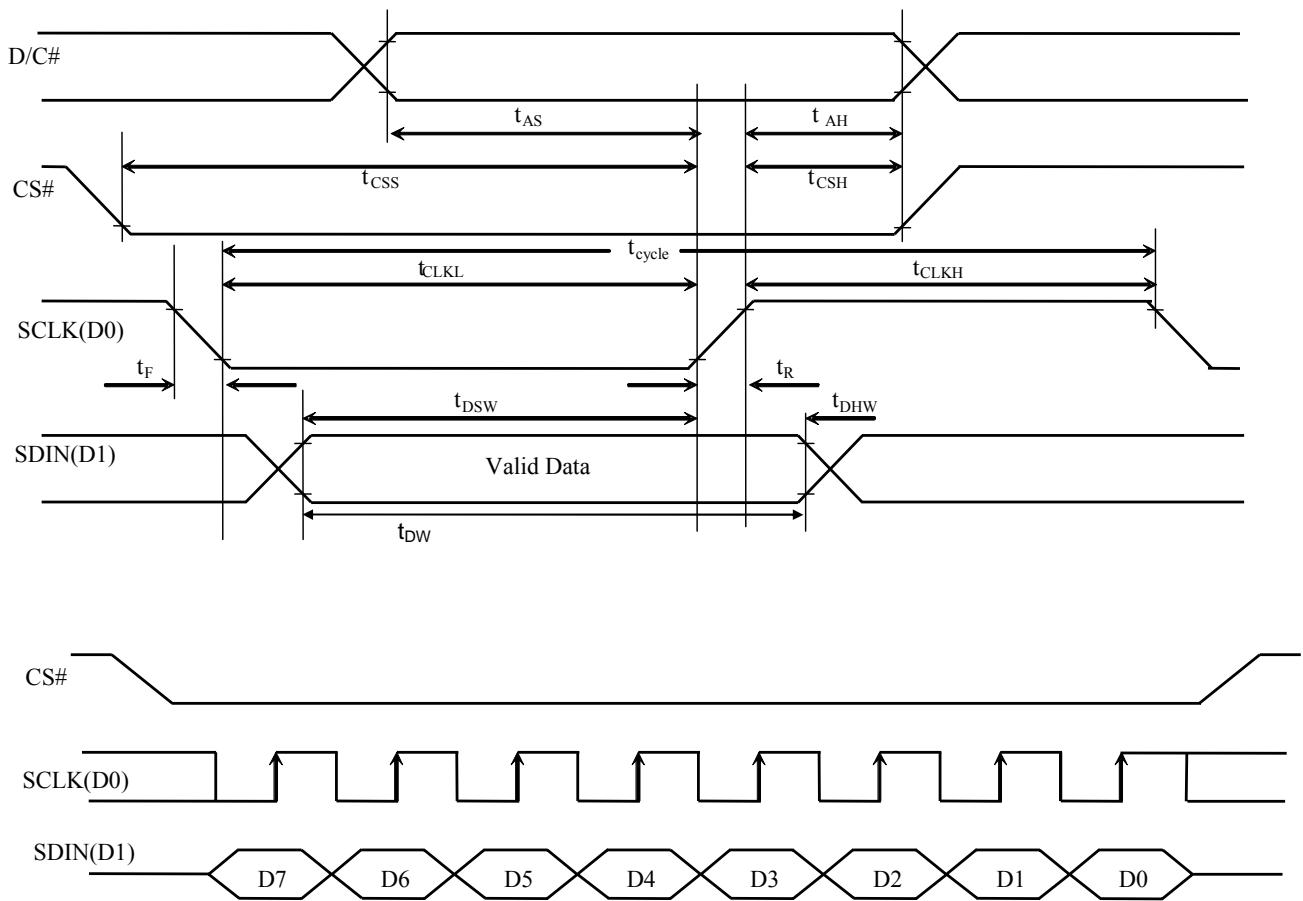
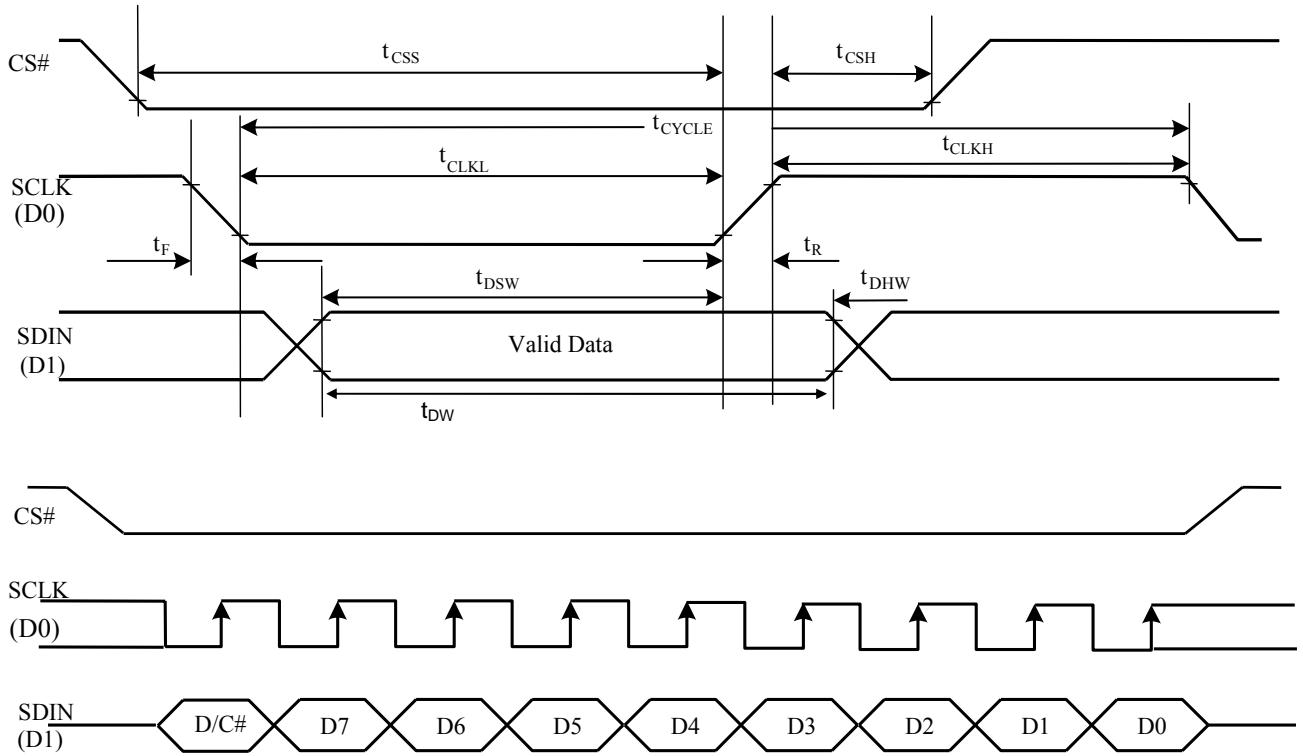


Table 13-5 : Serial Interface Timing Characteristics (3-wire SPI)

($V_{DD} - V_{SS} = 1.65V\sim 3.3V$, $T_A = 25^\circ C$)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	100	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	50	-	-	ns
t_{DW}	Data Write Time	55	-	-	ns
t_{DSW}	Write Data Setup Time	15	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{CLKL}	Clock Low Time	50	-	-	ns
t_{CLKH}	Clock High Time	50	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns

Figure 13-4 : Serial interface characteristics (3-wire SPI)



Conditions:

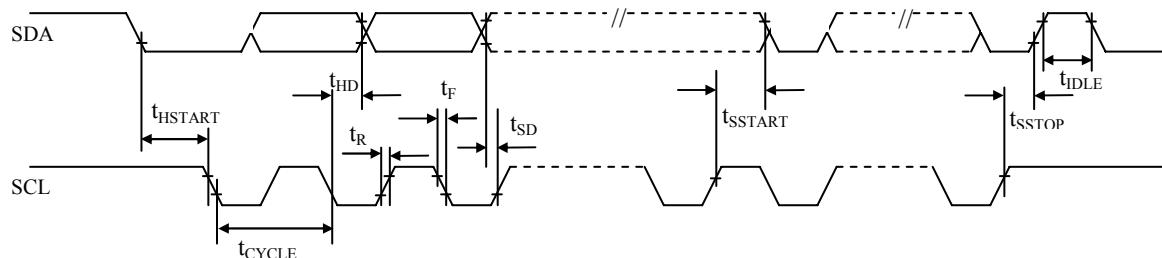
$V_{DD} - V_{SS} = 1.65V \sim 3.3V$

$T_A = 25^\circ C$

Table 13-6 : I²C Interface Timing Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	2.5	-	-	us
t_{HSTART}	Start condition Hold Time	0.6	-	-	us
t_{HD}	Data Hold Time (for "SDA _{OUT} " pin)	0	-	-	ns
	Data Hold Time (for "SDA _{IN} " pin)	300	-	-	ns
t_{SD}	Data Setup Time	100	-	-	ns
t_{SSTART}	Start condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	-	us
t_{SSTOP}	Stop condition Setup Time	0.6	-	-	us
t_R	Rise Time for data and clock pin	-	-	300	ns
t_F	Fall Time for data and clock pin	-	-	300	ns
t_{IDLE}	Idle Time before a new transmission can start	1.3	-	-	us

Figure 13-5 : I²C interface Timing characteristics

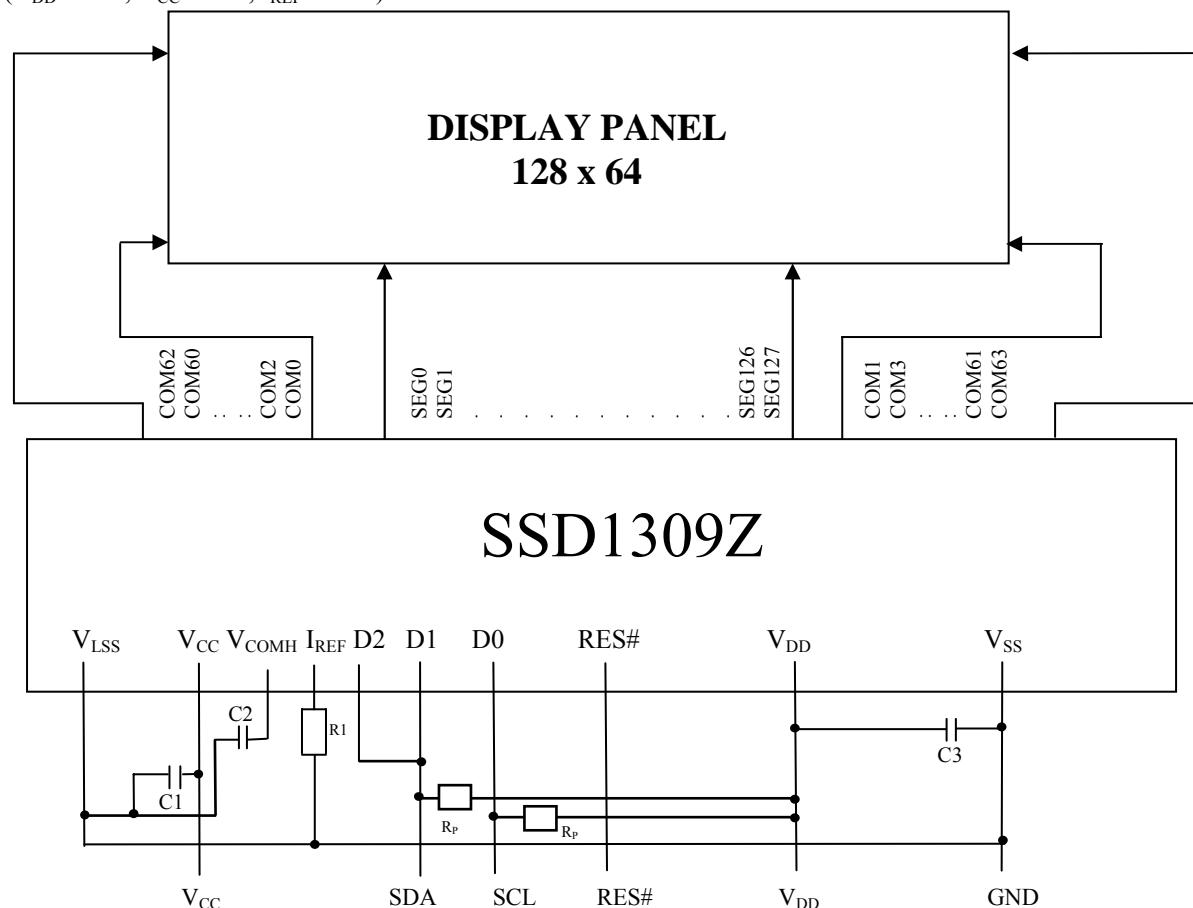


14 Application Example

Figure 14-1 : Application Example of SSD1309Z

The configuration for I²C interface mode is shown in the following diagram:

(V_{DD}=2.8V, V_{CC}=12V, I_{REF}=10uA)



Pin connected to MCU interface: D[2:0], RES#

Pin internally connected to V_{SS}: D[7:3], BS0, BS2, E, R/W#, CS#, CL, V_{SS1}

Pin internally connected to V_{DD}: BS1, CLS

TR[7:0] should be left open.

D/C# acts as SA0 for slave address selection ⁽³⁾

C1, C2: 2.2uF ⁽¹⁾

C3: 1.0uF ⁽¹⁾ place close to IC V_{DD} and V_{SS} pins on PCB

R_P : Pull up resistor

Voltage at I_{REF} = V_{CC} - 3V. For V_{CC} = 12V, I_{REF} = 10uA:

R1 = (Voltage at I_{REF} - V_{SS}) / I_{REF}

$$\approx (12-3)V / 10uA$$

$$= 900K\Omega$$

Note

⁽¹⁾ The capacitor value is recommended value. Select appropriate value against module application.

⁽²⁾ Die gold bump face down.

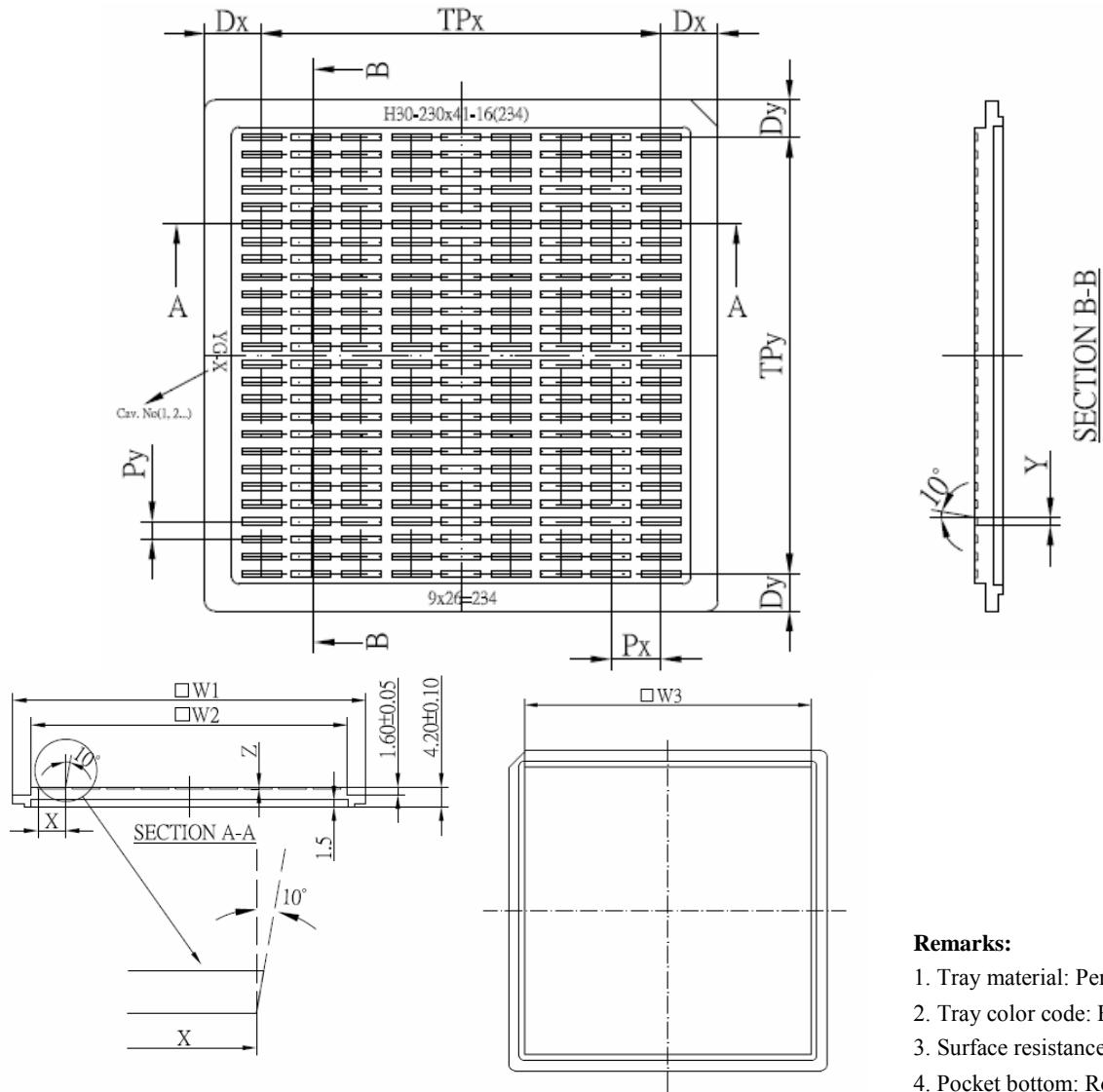
⁽³⁾ Refer to Section 8.1.5 for details.

⁽⁴⁾ It is recommended to tie V_{LSS} and V_{SS} at one common ground point to minimize circulating ground noise.

15 PACKAGE INFORMATION

15.1 SSD1309Z Die Tray Information

Figure 15-1: SSD1309Z die tray information



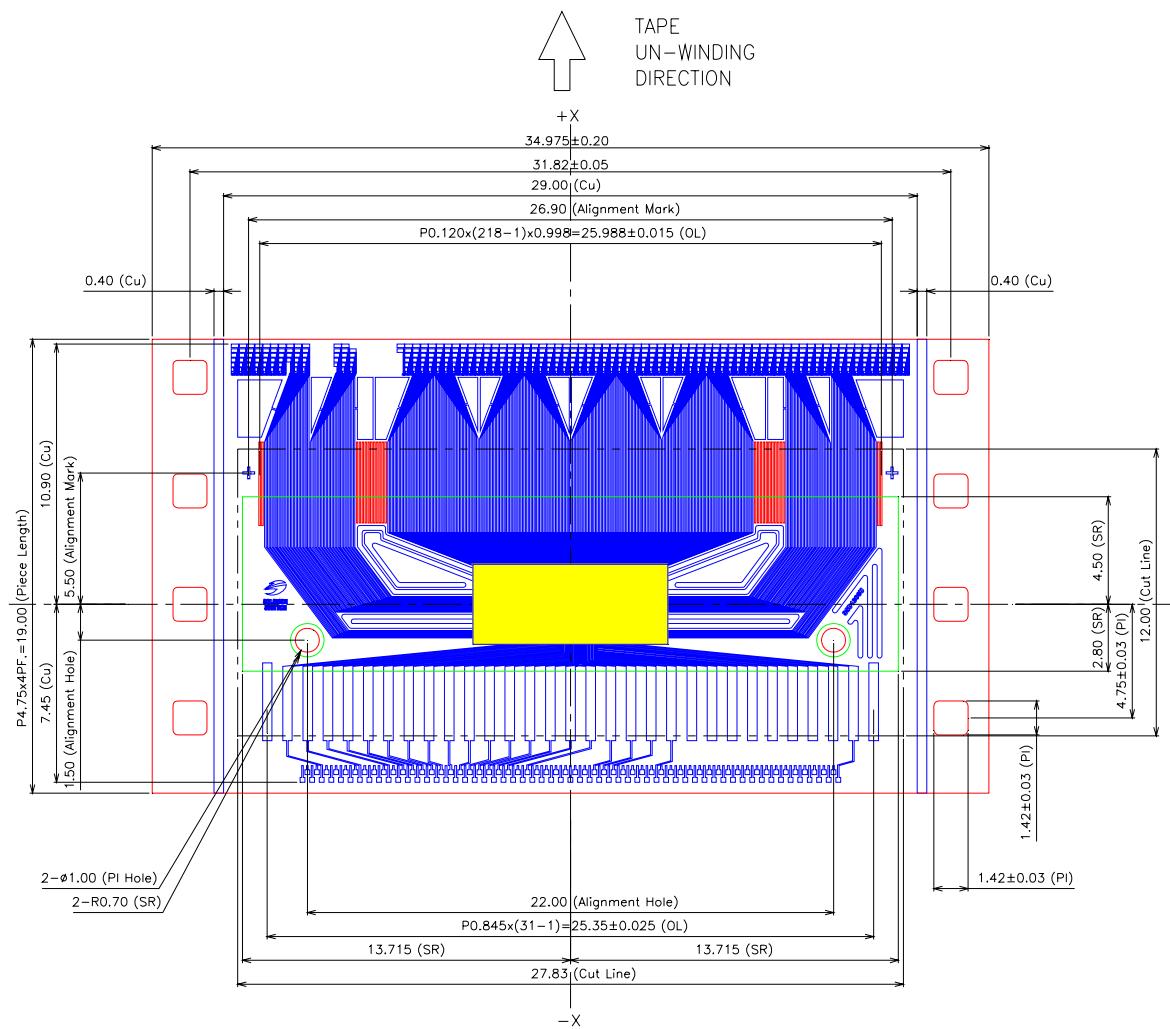
Remarks:

1. Tray material: Permanent Antistatic
2. Tray color code: Black
3. Surface resistance $10^9 \sim 10^{12} \Omega$
4. Pocket bottom: Rough Surface

Parameter	Dimensions	
	mm	(mil)
W ₁	76.00 ± 0.10	(2992)
W ₂	68.00 ± 0.10	(2677)
W ₃	68.30 ± 0.10	(2689)
D _X	8.40 ± 0.10	(331)
T _{Px}	59.20 ± 0.10	(2331)
D _Y	5.50 ± 0.10	(217)
T _{Py}	65.00 ± 0.10	(2559)
P _x	7.40 ± 0.05	(291)
P _y	2.60 ± 0.05	(102)
X	5.85 ± 0.05	(230)
Y	1.02 ± 0.05	(41)
Z	0.40 ± 0.05	(16)
N (pocket number)	234	

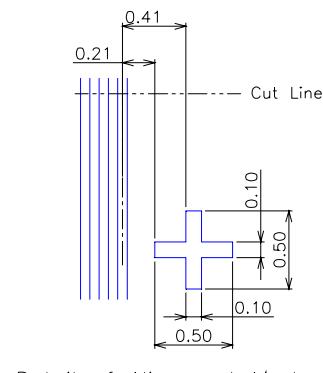
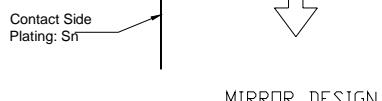
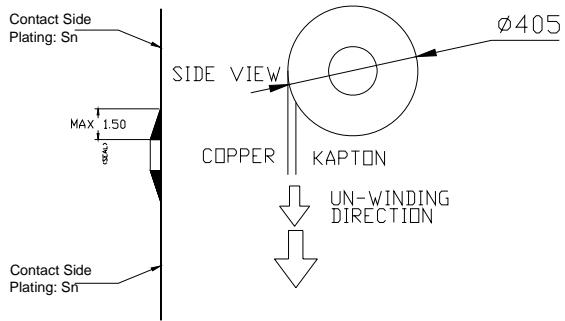
15.2 SSD1309UR1 Detail Dimension

Figure 15-2 SSD1309UR1 Detail Dimension



NOTE:

1. GENERAL TOLERANCE: ±0.05mm
2. MATERIAL
 - PI: 38±3.5µm
 - CU: 8±2µm
 - SR: 10±5µm
 - OTHER TOLERANCE: ±0.200mm
3. SN PLATING: 0.20±0.05µm
4. TAPESITE: 4 SPH, 19.0mm



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